



PY32F040-EP Datasheet

32-bit ARM[®] Cortex[®]-M0+ Microcontroller



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Features

- Core
 - ARM® 32-bit Cortex®-M0+ CPU
 - Frequency up to 24 MHz
- Memories
 - Up to 128 KB Flash memory
 - Up to 16 KB SRAM
- Clock management
 - 24/8 MHz High-speed internal RC oscillator (HSI)
 - 32.768/23.552/38.912/39.168/43.008 kHz Low-speed internal RC oscillator (LSI)
 - 4 to 24 MHz High-speed external crystal oscillator (HSE)
 - 32.768 kHz Low-speed external crystal oscillator (LSE)
- Power management and reset
 - Operating voltage: 3.0 to 5.5 V
 - Low power modes : Sleep and Stop
 - Power-on/power-down reset (POR/PDR)
 - Brown-out reset (BOR)
 - Programmable voltage detector (PVD)
- General-purpose input and output (I/O)
 - Up to 58 I/Os, all available as external interrupts
- 7-channel DMA controller
- 1 x 12-bit ADC
 - Up to 16 external channels
 - Conversion range: 0 to V_{REF+}
- 2 x analog comparators
- 2-channel operational amplifier
- Support 8 * 32 / 4 * 40 LCD
- 13 timers
 - 1 x 16-bit advanced-control timer (TIM1)
 - 1 x 32-bit general-purpose timer (TIM2)
 - 5 x 16-bit general-purpose timers (TIM3/14/15/16/17)
 - 2 x basic timers (TIM6/TIM7)
 - 1 x low power timer (LPTIM)
 - 1 x independent watchdog timer (IWDG)
 - 1 x window watchdog timer (WWDG)
 - 1 x SysTick timer
- RTC
- Communication interfaces
 - 2 x serial peripheral interfaces (SPIs) with I²S interface multiplexed
 - 4 x universal synchronous/asynchronous transceivers (USARTs) with automatic baud rate detection, two with ISO7816, LIN and IrDA capability
 - 2 x I²C interfaces supporting standard mode (100 kHz), Fast mode (400 kHz), 7-bit/10-bit addressing mode
- Hardware CRC-32 module
- 32-bit Hardware divider(DIV)
- Unique UID
- Serial wire debug (SWD)
- Operating temperature: - 40 to 105 °C
- Packages: LQFP64(12*12)

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1. Introduction

The PY32F040-EP microcontrollers incorporate the high-performance ARM® 32-bit Cortex®-M0+ core operating at up to 24 MHz frequency, embedded memories with up to 128 KB Flash and 16 KB SRAM, and is available in multiple package options. The PY32F040-EP integrates multi-channel I²Cs, SPIs, USARTs and other communication peripherals, one 12-bit ADC, 13 timers, two comparators, two operational amplifiers, and one LCD driver.

The PY32F040-EP microcontrollers operate in the -40 to 105 °C temperature range, from a 3.0 to 5.5 V power supply, provides Sleep and Stop low-power operating modes, which can meet different low-power applications.

These features make the PY32F040-EP microcontrollers suitable for a wide range of applications such as controllers, portable devices, PC peripherals, gaming and GPS platforms, industrial applications.

Table 1-1 PY32F040-EP series product features and peripheral counts

Peripherals		PY32F040R1BT7-EP
Flash (KB)		128
SRAM (KB)		16
Timers	Advanced control	1 (16-bit)
	General purpose	5 (16-bit)
		1(32-bit)
	Basic	2
	Low power	1
	SysTick	1
	Watchdog	2
Comm. interfaces	SPI[I ² S]	2[2]
	I ² C	2
	USART	4
DMA		7ch
RTC		Yes
GPIOs		58
12-bit ADC (external + internal)		1 (16 + 5)
Comparators		2
OPA		2
LCD		8 * 32 / 4 * 40
Max. CPU frequency		24 MHz
Operating voltage		3.0 to 5.5 V
Operating temperature		- 40 to 105 °C
Packages		LQFP64(12*12)

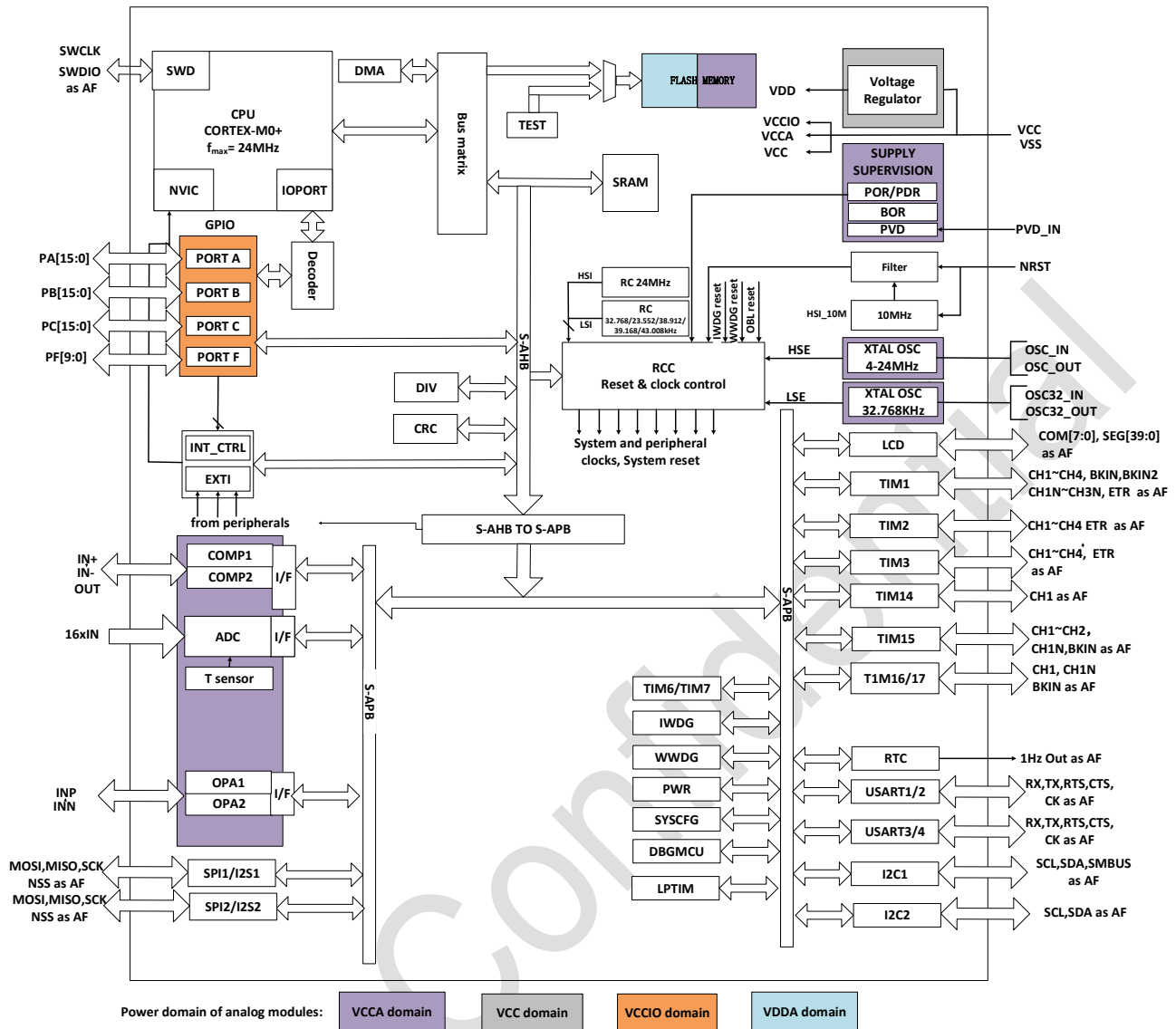


Figure 1-1 System block diagram

2. Functional overview

2.1. Arm®-Cortex®-M0+ core

The Arm® Cortex® -M0+ is an entry-level Arm 32-bit Cortex processor designed for embedded applications. It provides developers with significant benefits, including:

- Simple structure, easy to learn and program
- Ultra-low power consumption, energy-saving operation
- Reduced code density and more

The Arm® Cortex-M0+ processor is a 32-bit core optimized for area and power consumption and is a 2-stage pipeline Von Neumann architecture. The processor offers high-end processing hardware, including single-cycle multipliers, through a streamlined but powerful instruction set and an extensively optimized design. Moreover, it delivers the superior performance expected from a 32-bit architecture computer, with a higher coding density than other 8 and 16-bit microcontrollers.

The Cortex-M0+ is tightly coupled with a Nested Vectored Interrupt Controller (NVIC).

2.2. Memories

16 KB of embedded SRAM accessed by bytes (8 bits), half-word (16 bits) or word (32 bits).

The non-volatile memory is divided into two arrays:

- 128 KB of Main flash area for programs and data
- 13 KB of Information area:
 - Factory configuration bytes
 - Option bytes
 - UID bytes
 - System memory

The protection of Main flash area includes the following mechanisms:

- Read protection (RDP) prevents outside access.
- Write protection (WRP) prevents unwanted write operation (caused by confusion of Program memory pointer). The minimum protection unit for write protection is 8 KB.
- Option byte write protection is a special design for unlock.

2.3. Boot modes

At startup, the BOOT0 pin and boot selector option bit nBOOT are used to select one of the three boot options in the following table:

Table 2-1 Boot configuration

Boot mode configuration		Mode
nBOOT1 bit	BOOT0 pin	
X	0	Boot from Main flash
1	1	Boot from System memory
0	1	Boot from SRAM

The Boot loader is located in the System memory and is used to reprogram the Flash memory by using USART interface.

2.4. Clock system

System clock selection is performed on startup, however the internal RC 8 MHz oscillator is selected as default CPU clock on reset..After the program is operating the system clock frequency and system clock source can be reconfigured. The frequency clocks that can be selected are:

- A 24 MHz configurable internal high precision HSI clock
- A 32.768/23.552/38.912/39.168/43.008 kHz configurable internal LSI clock
- A 4 to 24 MHz HSE clock, and used to enable the CSS function to detect HSE. If CSS fails, the hardware will automatically convert the system clock to HSI, and software configures the HSI frequency. Simultaneously, CPU NMI interrupt is generated.
- A 32.768 kHz LSE clock.

The AHB clock can be divided based on the system clock, and the APB clock can be divided based on the AHB clock. The maximum frequency of the AHB and the APB domains is 24 MHz.

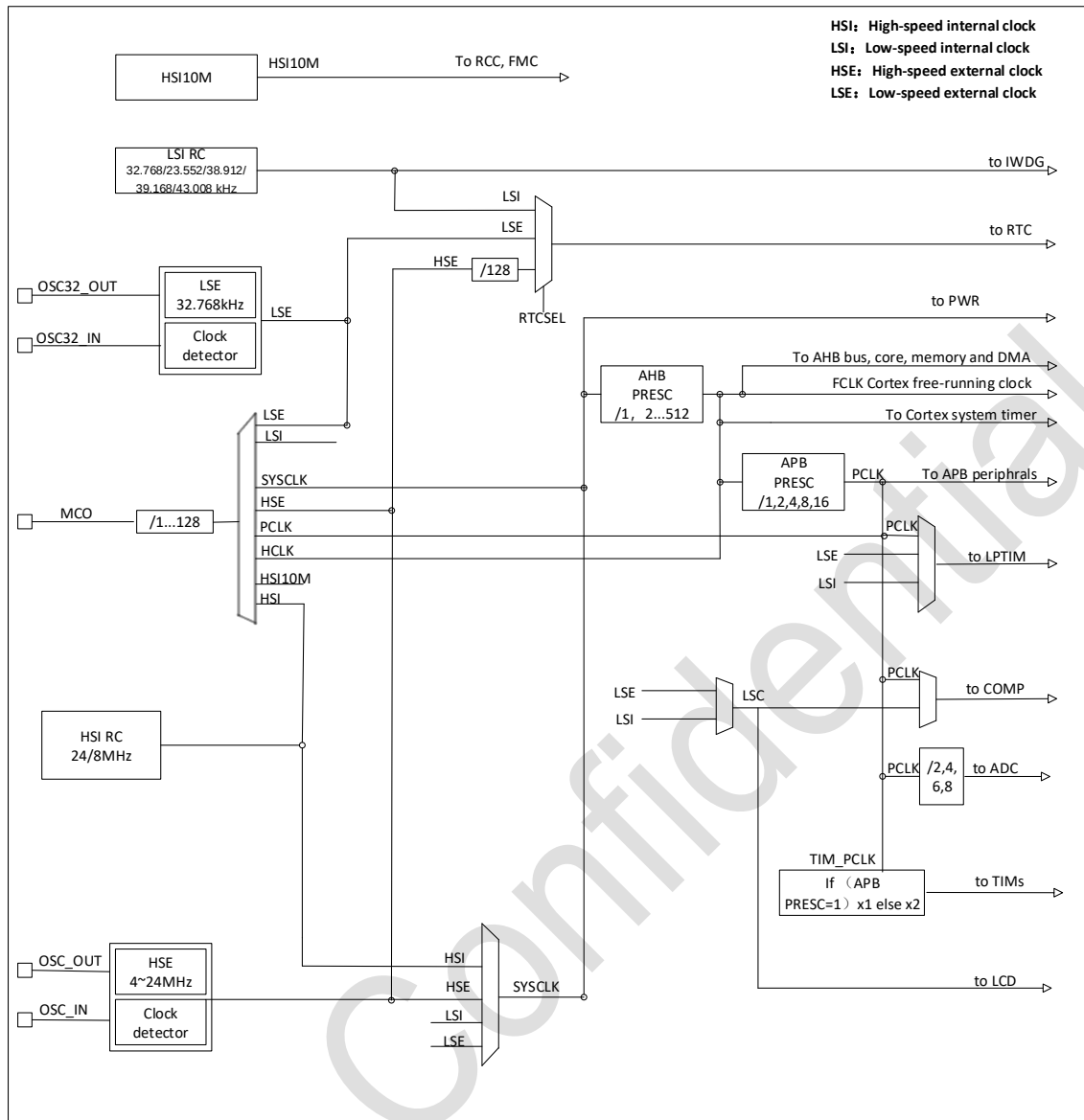


Figure 2-1 System clock structure diagram

2.5. Power management

2.5.1. Power block diagram

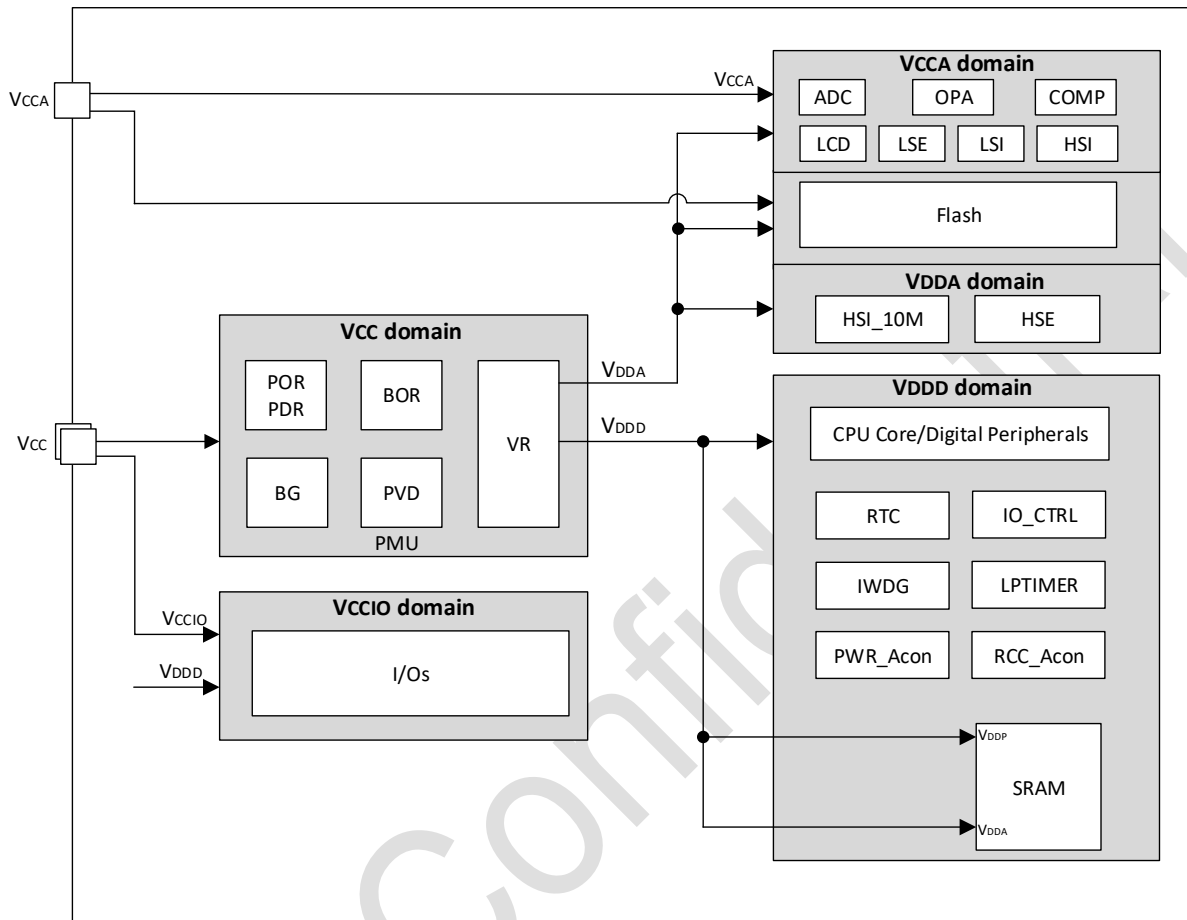


Figure 2-2 Power block diagram

Table 2-2 Power block diagram

No.	Power supply	Power value	Descriptions
1	V _{CC}	3.0 to 5.5 V	External power supply for I/Os and the internal regulator. It is provided externally through V _{CC} pins.
2	V _{CCA}	3.0 to 5.5 V	External analog power supply for ADC,COMP,OPA,LCD,RCs.It is provided externally through V _{CCA} pins..
3	V _{DDx} (V _{DDD} /V _{DDA})	1.2 V/1.0 V/0.9 V/0.8 V	Two embedded linear voltage regulators, MR and LPR, supply most of digital circuitry,SRAM in the device. When the MR is powered, it outputs 1.2 V. When entering the Stop mode it powered by MR or LPR(LPR.PWR_CR1 register),and the LPR output is determined to be 1.2 V/1.0 V/0.9 V/0.8 V(VOS.PWR_CR1 register).

2.5.2. Power monitoring

2.5.2.1. Power on reset /power-down reset(POR/PDR)

The power-on reset (POR) and power-down reset (PDR) module is designed in the chip to provide power-on and power-down reset for the chip. The module keeps working in all modes.

2.5.2.2. Brown-out reset (BOR)

In addition to POR/ PDR, BOR (Brown-out reset) is also implemented. BOR can only be enabled and disabled through the option byte .

When the BOR is turned on, the BOR threshold can be selected by the option byte.

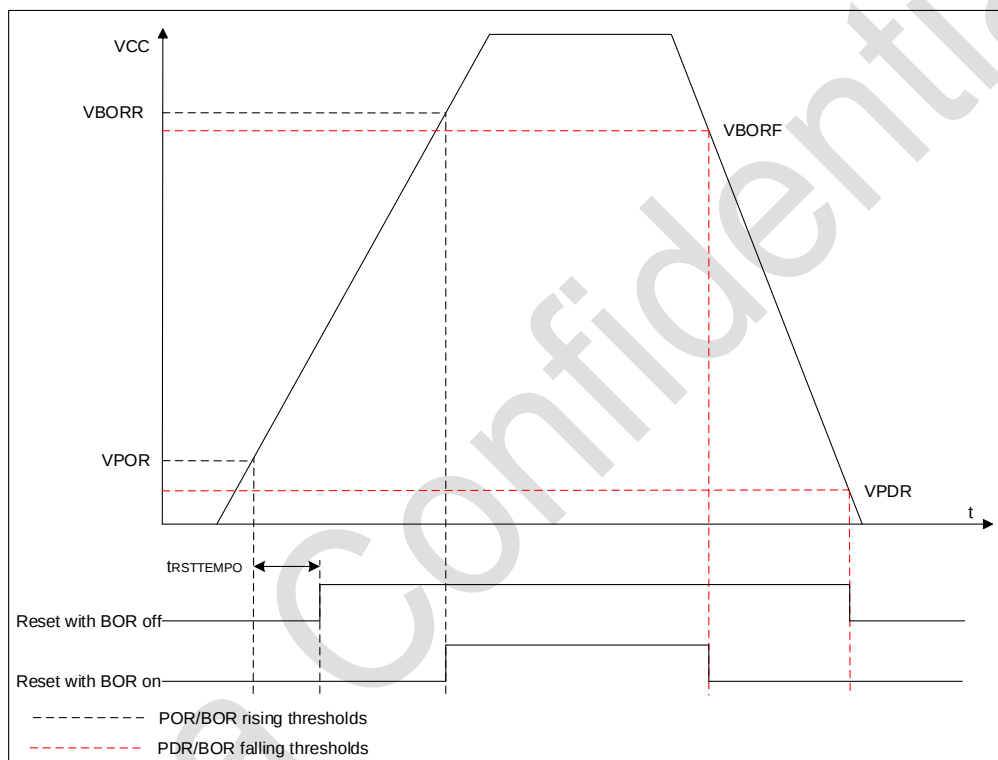


Figure 2-3 POR/PDR/BOR threshold

2.5.2.3. Programmable voltage detector (PVD)

Programmable voltage detector (PVD) module can be used to detect the V_{CC} power supply and the voltage of the PB7 pin, and the detection point is configured through the register. When V_{CC} is higher or lower than the detection point of PVD , the corresponding reset flag is generated.

This event is internally connected to line 16 of EXTI , depending on the rising/falling edge configuration of EXTI line 16, when V_{CC} rises above the detection point of PVD, or V_{CC} falls below the detection point of PVD, an interrupt is generated. In the service program, users can perform urgent shutdown tasks.

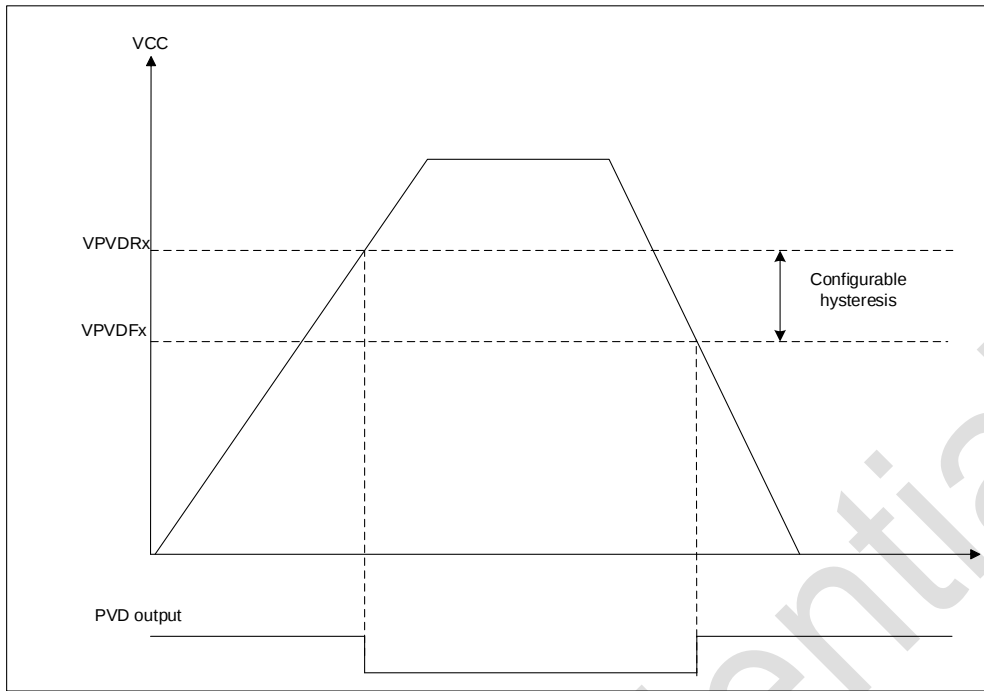


Figure 2-4 PVD threshold

2.5.3. Voltage regulator

The regulator has two operating modes:

- Main regulator (MR) is used in normal operating mode(Run).
- Low power regulator (LPR) can be used in Stop mode where the power demand is reduced.

2.5.4. Low-power mode

In addition to the normal operating mode, the chip has 2 low-power modes:

- Sleep mode: Peripherals can be configured to keep working when the CPU clock is off (NVIC, SysTick, etc.). It is recommended only to enable the modules that must work, and close the module after the module works.
- Stop mode: In this mode, the contents of SRAM and registers are maintained, HSI and HSE are turned off, and most modules of clocks in the VDDD domain are stopped. GPIO, PVD, COMP output, RTC and LPTIM can wake up Stop mode.

2.6. Reset

Two resets are designed in the chip: power reset and system reset.

2.6.1. Power reset

A power reset occurs in the following situations:

- Power-on/power-down reset (POR/PDR)
- Brown-out Reset (BOR)

2.6.2. System reset

A system reset occurs when the following events occur:

- Reset of NRST pin
- Windowed watchdog reset (WWDG)
- Independent watchdog reset (IWDG)
- SYSRESETREQ software reset
- Option byte load reset (OBL)

2.7. General-purpose inputs and outputs (GPIOs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. The I/O configuration can be locked if needed following a specific sequence in order to avoid spurious writing to the I/Os registers.

2.8. Direct memory access controller (DMA)

Direct memory access (DMA) is used in order to provide a high-speed data transfer between peripherals and memory as well as from memory to memory. Data can be quickly moved by DMA without any CPU actions. This keeps the CPU resources free for other operations.

The DMA controller have 7 channels in total, each one dedicated to manage memory access requests from one or more peripherals. Each controller has an arbiter for handling the priority between DMA requests.

The DMA supports:

- Single AHB Master
- Support peripherals to memory, the memory to the peripherals, memory to memory and peripherals to peripheral data transmission
- On-chip memory devices, such as Flash, an SRAM, AHB and APB peripherals, as the source and target
- All DMA channel can be independent configuration:
 - Each channel is associated either with a DMA request signal from a peripheral or with a software trigger in a memory-to-memory transfer. This configuration is done by software.
 - The priority between requests is programmable by software (4 levels per channel: very high, high, medium, low) and, in equal cases, by hardware (such as a request for channel 1 taking precedence over a request for channel 2).
 - The transfer sizes of the source and destination are independent (byte, half word, word), simulating packing and unpacking. The source and destination addresses must be aligned by data size.
 - Programmable number of data to be transferred: 0 to 65535
- Each channel generates an interrupt request. Each interrupt request is caused by one of three DMA events: transfer completion, half-transfer, or transfer error.

2.9. Interrupts and events

The PY32F040-EP handles exceptions through the Cortex-M0+ processor's embedded a nested vectored interrupt controller (NVIC) and an extended interrupt/event controller (EXTI).

2.9.1. Nested vectored interrupt controller (NVIC)

NVIC is a tightly coupled IP inside the Cortex-M0+ processor. The NVIC can handle NMI (Non-Mas-kable Interrupts) and maskable external interrupts from outside the processor and Cortex-M0+ internal exceptions. NVIC provides flexible priority management.

The tight coupling of the processor core to the NVIC greatly reduces the delay between an interrupt event and the initiation of the corresponding interrupt service routine (ISR). The ISR vectors are listed in a vector table, stored at a base address of the NVIC. The vector table base address determines the vector address of the ISR to execute, and the ISR is used as the offset composed of serial numbers.

If a high-priority interrupt event occurs and a low-priority interrupt event is just waiting to be serviced, the later-arriving high-priority interrupt event will be serviced first. Another optimization is called tail-chaining. When returning from a high-priority ISR and then starting a pending low-priority ISR, unnecessary pushes and pops of processor contexts will be skipped. This reduces latency and improves power efficiency.

NVIC features:

- Low latency interrupt handling
- Level 4 interrupt priority
- Supports one NMI interrupt
- Support 30 maskable external interrupts
- High-priority interrupts can interrupt low-priority interrupt responses
- Support tail-chaining optimization
- Hardware interrupt vector retrieval

2.9.2. Extended interrupt/event controller (EXTI)

EXTI adds flexibility to handle physical wire events and generates wake-up events when the processor wakes up from Stop mode.

The EXTI controller has multiple channels, including up to 58 GPIOs can be connected to the 16 EXTI lines, 1 PVD output, 2 COMP outputs, RTC and LPTIM wake-up signals. GPIO, PVD and COMP can be configured to be triggered by a rising edge, falling edge or double edge. Any GPIO signal can be configured as EXTI0 to 15 channel through the select signal.

- Each EXTI line can be independently masked through registers.
- The EXTI controller can capture pulses shorter than the internal clock period.
- Registers in the EXTI controller latch each event. Even in Stop mode, after the processor wakes up from Stop mode, it can identify the wake-up source or identify the GPIO and event that caused the interrupt.

2.10. Analog-to-digital converter (ADC)

The 12-bit analog-to-digital converter has up to 16 external and 5 internal channels.

The ADC internal voltage reference: V_{REFBUF} (1.5 V, 2.048 V, 2.5 V) or the power supply voltage V_{CCA} .

The internal channels are: T_{S_VIN} , V_{REFINT} , $V_{CCA}/3$, OPA1, OPA2.

- A/D conversion of the various channels can be performed in single, continuous, scan or discontinuous mode. The result of the ADC is stored in a left-aligned or right-aligned 16-bit data register.
- The analog watchdog feature allows the application to detect if the input voltage goes outside the user-defined higher or lower thresholds.
- An efficient low-power mode is implemented to allow very low consumption at low frequency.
- Analog watchdog for automatic voltage monitoring, generating interrupts and trigger for selected timers

2.11. Comparators (COMP)

Two general purpose comparators are integrated in the chip, namely COMP1/2. It can be used as a separate module or in combination with timer. Comparators can be triggered by analog signal to generate low-power mode wake-up function, analog signal conditioning, Cycle by cycle current control loop when connected with PWM output from timer. COMP features are summarized as follows:

- Voltage comparison function is supported. Each comparator has configurable positive or negative input for flexible voltage selection:
 - Multiple I/O pins
 - 64 steps voltage of $V_{CCA}/V_{REFBUF}/V_{REF1P2}$
 - V_{REFINT}
 - Temperature sensor output
 - OPA output
- Programmable speed and power consumption
- Rail to Rail
- Hysteresis function
- The output can be triggered by a connection to the I/O or timer input
- Each COMP has interrupt generation capability and is used to wake up the chip from low power mode (sleep/stop) (via EXTI)
- Provides software to configure the digital filtering time to enhance the anti-interference capability of the chip
- Supports the Window COMP function

2.12. Operational amplifier (OPA)

The OPA1/2 module can be flexibly configured and is suitable for simple amplifiers. The two internal OPA can be cascaded using external resistors.

OPA features are summarized as follows:

- Two independently configured operational amps
- OPA input range is 0 to V_{CCA} , output range is 0.2 V to $V_{CCA}-0.2$ V
- Can be configured for the following models
 - General operational mode (general purpose OPA)

2.13. Liquid crystal display (LCD) controller

The LCD controller is a digital controller/driver for monochrome passive liquid crystal display (LCD), with up to 8 common terminals (COM) and 40 segment terminals (SEG) to drive 160 (4 * 40) or 256 (8 * 32) LCD pixels. The exact number of terminals depends on the device pins described in the data manual. LCD functions are summarized as follows:

- Highly flexible frame rate control
- Support static, 1/4, 1/6, and 1/8 duty cycle
- Support 1/2, 1/3 bias voltage
- Up to 16 registers LCD data RAM
- By software configuration of LCD contrast
- 2 kinds of waveform generation
 - Internal resistance divider, external resistance divider
 - By way of internal resistance of the software configuration partial pressure power consumption, so as to match the capacitance charge needed for the LCD panel
- Support low power consumption modes: LCD controller can be on the Run, Sleep and Stop mode for display
- Configurable frame interrupt
- Support LCD flashing function and configuration of multiple flicker frequency
- Unused LCD segments and public pin can be configured to digital or analog functions

2.14. Hardware divider (DIV)

The Hardware divider is a 32-bit signed/unsigned integer hardware divider.

DIV features:

- Support 32-bit division
- The data in the register cannot be changed while the current division is not finished
- Configurable signed/unsigned integer division calculation
- 32-bit divisor, 32-bit divisor
- Outputs 32-bit quotient and 32-bit remainder
- Divide-by-zero warning flag bit, end-of-division flag bit
- 8 clock cycles to complete a division operation
- Write the divisor register to trigger the start of the division circuit
- After writing the divisor, when reading the quotient and remainder registers, you need to wait for the completion flag DIV_END
- When the divisor is 0, the result of quotient and remainder is 0

2.15. Timers

Table 2-3 compares the features of the different timers.

Table 2-3 Timer feature comparison

Timer type	Timer	Counter resolution	Counter type	Prescaler factor	DMA	Capture /compare channels	Complementary outputs
Advanced control	TIM1	16-bit	up, down, up/down	1- 65536	Yes	4	3
General purpose	TIM2	32-bit	up, down, up/down	1- 65536	Yes	4	-
General purpose	TIM3	16-bit	up, down, up/down	1- 65536	Yes	4	-
	TIM14	16-bit	up	1- 65536	-	1	-
	TIM15	16-bit	up	1- 65536	Yes	2	1
	TIM16 TIM17	16-bit	up	1- 65536	Yes	1	1
Basic	TIM6 TIM7	16-bit	up	1- 65536	Yes	-	-

2.15.1. Advanced-control timer (TIM1)

The advanced-control timer (TIM1) is consist of a 16-bit auto-reload counter driven by a programmable prescaler. It can be used in various scenarios, including pulse length measurement of input signals (input capture) or generating output waveforms (output compare, output PWM, complementary PWM with dead-time insertion).

The four independent channels can be used for:

- Input capture
- Output compare
- PWM generation (edge or center-aligned mode)
- Single pulse mode output

If configured as a standard 16-bit timer, it has the same features as the TIMx timer. If configured as the 16-bit PWM generator, it has full modulation capability (0-100%).

The counter can be frozen in debug mode.

Many features are shared with those of the standard timers which have the same architecture. The advanced control timer can therefore work together with the other timers by the Timer Link feature for synchronization or event chaining.

TIM1 supports the DMA function.

2.15.2. General-purpose timers

2.15.2.1. TIM2/TIM3

The general-purpose timers TIM2/TIM3 are consist of 32/16-bit auto-reload counters and a 32/16-bit prescaler. There are four independent channels each for input capture/output compare, PWM or one-pulse mode output.

- They can work with the TIM1 by the Timer Link.
- TIM2/TIM3 supports DMA function.

- This timer is capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 3 hall-effect sensors.
- The counter can be frozen in debug mode.

2.15.2.2. TIM14

- The general-purpose timer (TIM14) is consist of a 16-bit auto-reload counter driven by a programmable prescaler.
- TIM14 features one single channel for input capture/output compare, PWM or one-pulse mode output.
- The counter can be frozen in debug mode.

2.15.2.3. TIM15/TIM16/TIM17

- The general-purpose timer (TIM15, TIM16 and TIM17) is consist of a 16-bit auto-reload counter driven by a programmable prescaler.
- TIM16/TIM17 features one single channel for input capture/output compare, PWM or one-pulse mode output.
- TIM15 features two single channel for input capture/output compare, PWM or one-pulse mode output.
- TIM15/TIM16/TIM17 have complementary outputs with dead time.
- TIM15/TIM16/TIM17 supports DMA function.
- The counter can be frozen in debug mode.

2.15.3. Basic timers (TIM6/TIM7)

- The basic timer (TIM6/TIM7) is consist of a 16-bit auto-reload upcounter driven by their programmable prescaler respectively.
- Generate interrupt/DMA request on update event (counter overflow).

2.15.4. Low power timer (LPTIM)

- LPTIM is a 16 -bit upcounter with a 3-bit prescaler and support single and continuous count.
- LPTIM can be configured as a Stop mode wake-up source.
- The counter can be frozen in debug mode.

2.15.5. Independent watchdog (IWDG)

Independent watchdog (IWDG) is integrated in the chip, and this module has the characteristics of high-security level, accurate timing and flexible use. IWDG finds and resolves functional confusion due to software failure and triggers a system reset when the counter reaches the specified timeout value.

- The IWDG is clocked by LSI, so even if the main clock fails, it can keep working.
- IWDG is the best suited for applications that require the watchdog as a standalone process outside of the main application and do not have high timing accuracy constraints.
- Controlling of option byte can enable IWDG hardware mode.
- IWDG is the wake-up source of Stop mode, which wakes up Stop mode by reset.

- The counter can be frozen in debug mode.

2.15.6. System window watchdog (WWDG)

The system window watchdog is based on a 7-bit downcounter that can be set as free running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the APB clock (PCLK). It has an early warning interrupt capability, and the counter can be frozen in debug mode.

2.15.7. SysTick timer

This timer is dedicated to real-time operating systems, but could also be used as a standard down counter.

SysTick features:

- A 24-bit down counter
- Auto-reload capability
- Maskable system interrupt generation when the counter reaches 0

2.16. Real-time clock (RTC)

The RTC is an independent counter. It has a set of continuous counting counters, which can provide a clock calendar function under the corresponding software configuration. Modifying the value of the counter can reset the current time and date of the system.

- RTC is a 32-bit programmable counter with a prescaler factor of up to 220 bits.
- The RTC counter clock source can be LSE, LSI and HSE/128.
- RTC can generate alarm interrupt, second interrupt and overflow interrupt (maskable).
- RTC supports clock calibration.
- RTC can be frozen in debug mode.

2.17. Cyclic redundancy check cell(CRC)

The CRC computing unit is based on a fixed generation polynomial to obtain 32-bit CRC computing results. In other applications, CRC technology is mainly used to verify the correctness and integrity of data transmission or data storage.

2.18. System configuration controller (SYSCFG)

The SYSCFG module provides the following functions:

- Enable and disable I²C type IO filter
- Mapping the initial program area according to different boot modes
- DMA peripheral channel selection control
- TIMx cascade control
- Enable and disable PVD Lock
- Enable and disable Cortex-M0+ LOCKUP
- Enable and disable Noise filter for all GPIOs

2.19. Debug support(DBG)

The MCU DBG module assists the debugger with the following functions:

- Support Sleep mode, Stop mode
- When the CPU enters the HALT mode, the control timer or watchdog stops counting or continues counting
- Block I²C1 and I²C2 SMBUS timeouts when the CPU is in HALT mode

The MCUIDBG register also provides chip ID encoding. This ID encoding can be accessed by a JTAG or SW debug interface, or by a user program.

2.20. Inter-integrated circuit interface (I²C)

The I²C (inter-integrated circuit) bus interface handles communications between the microcontroller and the serial I²C bus. It provides multimaster capability, and controls all I²C bus-specific sequencing, protocol, arbitration and timing. It supports Standard-mode (Sm) and Fast-mode (Fm) .

I²C features:

- Multimaster capability : can be Master or Slave
- Support different communication speeds
 - Standard mode (Sm): up to 100 kHz
 - Fast mode (Fm): up to 400 kHz
- As Master
 - Generate clock
 - Generation of start and stop
- As Slave
 - Programmable I2C address detection
 - Dual-address capability that responds to two secondary addresses
 - Discovery of the STOP bit
- 7-bit/10-bit addressing mode
- General call
- Status flag
 - Transmit/receive mode flags
 - Byte transfer complete flag
 - I²C busy flag bit
- Error flag
 - Master arbitration loss
 - ACK failure after address/data transfer
 - Start/stop error
 - Overrun/Underrun (clock stretching function disable)
- Optional clock stretching
- Single-byte buffer with DMA capability
- Software reset

- Analog noise filter function
- Hardware PEC (packet error checking) generation and verification with ACK control
- Support SMBus

2.21. Universal synchronous/asynchronous receiver transmitter (USART)

The PY32F040-EP contains 4 USARTs, two of USARTs (USART1 and USART2) support ISO7816, LIN, and IrDA.

The USARTs provide a flexible method for full-duplex data exchange with external devices using the industry-standard NRZ asynchronous serial data format. The USART utilizes a fractional baud rate generator to provide a wide range of baud rate options.

It supports simultaneous one-way communication and half-duplex single-wire communication, and it also allows multi-processor communication.

Automatic baud rate detection is supported.

High-speed data communication can be achieved by using the DMA method of the multi-buffer configuration.

USARTs features:

- Full-duplex asynchronous communication
- NRZ standard format
- Configurable 16 times or 8 times oversampling for increased flexibility in speed and clock tolerance
- Programmable baud rate shared by transmit and receive, up to 4.5 Mbit/s
- Automatic baud rate detection
- Programmable data length of 8 or 9 bits
- Configurable STOP bits (0.5, 1, 1 or 2 bits)
- Synchronous mode and clock output function for synchronous communication
- Single-wire half-duplex communication
- Independent transmit and receive enable bits
- Hardware flow control
- Receive/transmit bytes by DMA buffer
- Detection flag
 - Receive full buffer
 - Send empty buffer
 - End of transmission
- Parity control
 - Send check digit
 - Check the received data
- Flagged interrupt sources
 - CTS change

- Send empty register
- Send completed
- Receive full data register
- Bus idle detected
- Overflow error
- Frame error
- Noise operation
- Error detection
- Multiprocessor communication
 - If the address does not match, enter silent mode
- Wake-up from silent mode: by idle detection and address flag detection

2.22. Serial peripheral interface (SPI)

The PY32F040-EP contains two SPIs. SPIs allow the chip to communicate with external devices in half-duplex, full-duplex, and simplex synchronous serial communication. This interface can be configured in Master mode and provides the serial clock (SCK) for external slave devices. The interface can also work in a multi-master configuration.

The SPI features are as follows:

- Master or Slave mode
- 3-wire full-duplex simultaneous transmission
- 2-wire half-duplex synchronous transmission (with bidirectional data line)
- 2-wire simplex synchronous transmission (no bidirectional data line)
- 8-bit or 16-bit transmission frame selection
- Support multi-master mode
- 8 Master mode baud rate prescale factors (Max $f_{PCLK}/2$)
- Slave mode frequency (Max $f_{PCLK}/4$)
- Both Master and Slave modes can be managed by software or hardware NSS: dynamic change of Master/Slave operating mode
- Programmable clock polarity and phase
- Programmable data order, MSB first or LSB first
- Dedicated transmit and receive flags that can trigger interrupts
- SPI bus busy status flag
- Motorola mode
- Interrupt-causing Master mode faults, overloads
- Two 32-bit Rx and Tx FIFOs with DMA capability

2.23. Serial wire debug (SWD)

An ARM SWD interface allows serial debugging tools to be connected to the PY32F040-EP.

3. Pinouts and pin descriptions

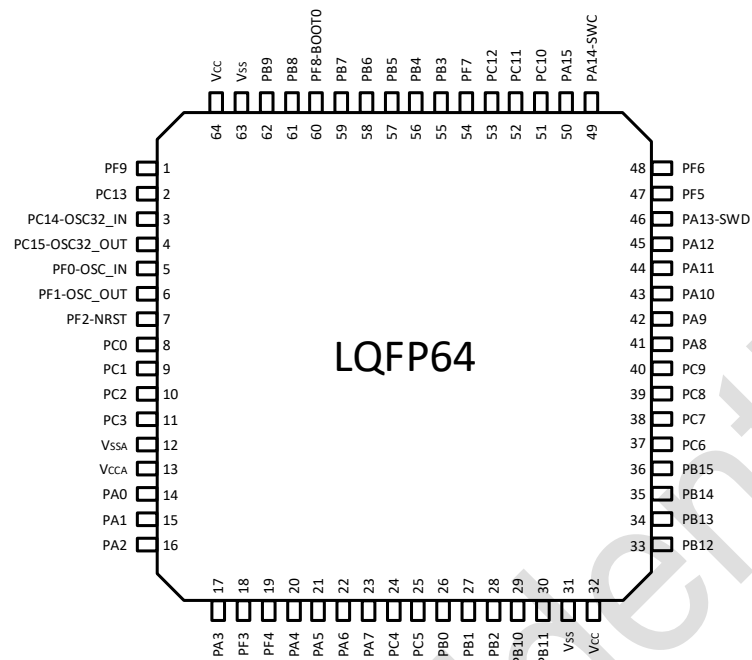


Figure 3-1 LQFP64 PY32F040R1BT7-EP Pinout1(Top view)

Table 3-1 Legend/abbreviations used in the pinout table

Name		Symbol	Definition
Pin type		S	Supply pin
		G	Ground pin
		I	Input-only pin
		I/O	Input / output pin
I/O structure		COM	Standard 5 V I/O, with Analog switch function supplied by V _{CCA}
		NRST	Bidirectional reset pin with embedded weak pull-up resistor
Notes		-	Unless otherwise specified, all ports are used as floating inputs between and after reset
Pin functions	Alternate functions	-	Function selected through GPIOx_AFR register
	Additional functions	-	Functions directly selected/enabled through peripheral registers

Table 3-2 Pin definitions

Packages	Reset	Port type	Port structure	Notes	Functions	
LQFP64 R1					Alternate functions	Additional functions
1	PF9	I/O	COM		-	-
2	PC13	I/O	COM		SPI1_SCK/I ² S1_CK	-
					TIM1_BKIN	
3	PC14	I/O	COM		TIM1_BKIN2	OSC32_IN
4	PC15	I/O	COM		TIM15_BKIN	OSC32_OUT
5	PF0-OSC_IN	I/O	COM		USART2_TX	OSC_IN
					TIM1_BKIN	
					TIM14_CH1	
6	PF1-OSC_OUT	I/O	COM		USART2_RX	OSC_OUT
					TIM1_CH1N	
					TIM15_CH1N	
7	PF2-NRST	I/O	NRST	(1)	TIM1_CH2	-
					EVENTOUT	
					MCO	
8	PC0	I/O	COM		EVENTOUT	ADC_IN10, COMP1_INN15, COMP2_INN0, SEG27
					SPI1_MISO/I ² S1_MCK	
					USART2_CTS	
					USART3_RTS	
9	PC1	I/O	COM		EVENTOUT	ADC_IN11, COMP1_INP1, COMP2_INN1, SEG26
					SPI1_MOSI/I ² S1_SD	
					USART2_RTS	
					USART3_CTS	
					TIM15_CH1	
10	PC2	I/O	COM		EVENTOUT	ADC_IN12, COMP1_INP2, COMP2_INN2, SEG25
					SPI2_MISO/I ² S2_MCK	
					USART3_TX	
					USART3_RX	
					TIM15_CH2	
11	PC3	I/O	COM		EVENTOUT	ADC_IN13, COMP1_INP3, COMP2_INN3, SEG24
					SPI2_MOSI/I ² S2_SD	
					USART3_RX	
					USART3_TX	
12	V _{SSA}	G			Ground	
13	V _{CCA}	S			Analog power supply	

Packages	Reset	Port type	Port structure	Notes	Functions	
LQFP64 R1					Alternate functions	Additional functions
14	PA0	I/O	COM		USART2_CTS TIM2_CH1_ETR USART4_TX COMP1_OUT SPI2_SCK/I ² S2_CK	ADC_IN0, COMP1_INP4, COMP1_INN0, COMP2_INP0, COMP2_INN4, SEG23
15	PA1	I/O	COM		EVENTOUT USART2_RTS TIM2_CH2 USART4_RX TIM15_CH1N I ² C1_SMBA SPI1_SCK/I ² S1_CK SPI2_MOSI/I ² S2_SD	ADC_IN1, COMP1_INP5, COMP1_INN1, COMP2_INP1, COMP2_INN5, SEG22
16	PA2	I/O	COM		TIM15_CH1 USART2_TX TIM2_CH3 COMP2_OUT SPI1_MOSI/I ² S1_SD SPI2_MISO/I ² S2_MCK	ADC_IN2, COMP1_INP6, COMP1_INN2, COMP2_INP2, SEG21
17	PA3	I/O	COM		EVENTOUT TIM15_CH2 USART2_RX TIM2_CH4 SPI2_MISO/I ² S2_MCK SPI2_NSS/I ² S2_WS	ADC_IN3, COMP1_INP7, COMP1_INN3, COMP2_INP3, SEG20
18	PF3	I/O	COM		EVENTOUT I ² C1_SCL I ² C2_SCL	-
19	PF4	I/O	COM		I ² C1_SDA I ² C2_SDA	-
20	PA4	I/O	COM		EVENTOUT SPI1_NSS/I ² S1_WS USART2_CK TIM14_CH1 SPI2_MOSI/I ² S2_SD USART2_TX	ADC_IN4, COMP1_INP8, COMP1_INN4, COMP2_INP4, SEG19

Packages					Functions	
LQFP64 R1	Reset	Port type	Port structure	Notes	Alternate functions	Additional functions
					PVD_OUT	
21	PA5	I/O	COM		EVENTOUT SPI1_SCK/I ² S1_CK TIM2_CH1_ETR USART3_TX	ADC_IN5, COMP1_INP9, COMP1_INN5, COMP2_INP5, SEG18, OPA2_OUT
22	PA6	I/O	COM		EVENTOUT SPI1_MISO/I ² S1_MCK TIM3_CH1 TIM1_BKIN USART3_CTS TIM16_CH1 COMP1_OUT	ADC_IN6, COMP1_INP10, COMP1_INN6, OPA2_INN, SEG17
23	PA7	I/O	COM		EVENTOUT SPI1_MOSI/I ² S1_SD TIM3_CH2 TIM1_CH1N TIM14_CH1 TIM17_CH1 COMP2_OUT	ADC_IN7, COMP1_INP11, COMP1_INN7, OPA2_INP, SEG16
24	PC4	I/O	COM		EVENTOUT USART3_TX SPI1_NSS/I ² S1_WS USART1_TX TIM2_CH1_ETR IR_OUT	ADC_IN14, COMP1_INN8, SEG15
25	PC5	I/O	COM		USART3_RX SPI1_MOSI/I ² S1_SD USART1_RX TIM2_CH2	ADC_IN15, COMP1_INN9, SEG14
26	PB0	I/O	COM		EVENTOUT TIM3_CH3 TIM1_CH2N USART3_CK COMP1_OUT SPI1_NSS/I ² S1_WS USART3_RX	ADC_IN8, COMP2_INN6, SEG13

Packages	Reset	Port type	Port structure	Notes	Functions	
LQFP64 R1					Alternate functions	Additional functions
27	PB1	I/O	COM		EVENTOUT TIM14_CH1 TIM3_CH4 TIM1_CH3N USART3_RTS	ADC_IN9, COMP2_INP6, COMP2_INN7, SEG12
28	PB2	I/O	COM		EVENTOUT SPI2_MISO/I ² S2_MCK USART3_TX	COMP2_INP7, COMP2_INN8, SEG11
29	PB10	I/O	COM		I ² C2_SCL TIM2_CH3 USART3_TX SPI2_SCK/I ² S2_CK COMP1_OUT USART2_RTS I ² C1_SCL	COMP2_INP8, SEG10
30	PB11	I/O	COM		EVENTOUT I ² C2_SDA TIM2_CH4 USART3_RX COMP2_OUT SPI2_MOSI/I ² S2_SD USART2_CTS I ² C1_SDA	SEG9
31	V _{SS}	G	-		Ground	
32	V _{CC}	S	-		Digital power supply	
33	PB12	I/O	COM		EVENTOUT SPI2_NSS/I ² S2_WS TIM1_BKIN USART3_CK TIM15_BKIN	COMP2_INN15, SEG8
34	PB13	I/O	COM		EVENTOUT SPI2_SCK/I ² S2_CK TIM1_CH1N USART3_CTS I ² C2_SCL MCO	COMP2_INP10, SEG7

Packages					Functions	
LQFP64 R1	Reset	Port type	Port structure	Notes	Alternate functions	Additional functions
					TIM15_CH1N	
					I ² C1_SCL	
35	PB14	I/O	COM		EVENTOUT	COMP2_INP11, SEG6
					SPI2_MISO/I ² S2_MCK	
					TIM15_CH1	
					TIM1_CH2N	
					USART3_RTS	
					I ² C2_SDA	
					I ² C1_SDA	
36	PB15	I/O	COM		EVENTOUT	SEG5
					SPI2_MOSI/I ² S2_SD	
					TIM15_CH2	
					TIM1_CH3N	
					TIM15_CH1N	
37	PC6	I/O	COM		TIM3_CH1	SEG4
					SPI2_SCK/I ² S2_CK	
					USART4_RX	
					TIM2_CH3	
38	PC7	I/O	COM		TIM3_CH2	SEG3
					SPI2_MISO/I ² S2_MCK	
					USART4_TX	
					TIM2_CH4	
39	PC8	I/O	COM		TIM3_CH3	SEG2
					SPI2_MOSI/I ² S2_SD	
					USART4_CTS	
					TIM1_CH1	
40	PC9	I/O	COM		TIM3_CH4	SEG1
					SPI2_NSS/I ² S2_WS	
					SPI1_SCK/I ² S1_CK	
					USART4_RTS	
					TIM1_CH2	
41	PA8	I/O	COM		EVENTOUT	COM0, OPA1_OUT
					MCO	
					USART1_CK	
					TIM1_CH1	
					SPI2_NSS	

Packages	Reset	Port type	Port structure	Notes	Functions	
LQFP64 R1					Alternate functions	Additional functions
					USART1_TX	
42	PA9	I/O	COM		EVENTOUT	COM1, OPA1_INP
					TIM15_BKIN	
					USART1_TX	
					TIM1_CH2	
					I ² C1_SCL	
					SPI2_MISO/I ² S2_MCK	
					MCO	
					I ² C2_SCL	
43	PA10	I/O	COM		EVENTOUT	COM2, OPA1_INN
					TIM17_BKIN	
					USART1_RX	
					TIM1_CH3	
					I ² C1_SDA	
					SPI2_MOSI/I ² S2_SD	
					I ² C2_SDA	
44	PA11	I/O	COM		EVENTOUT	SEG0
					USART1_CTS	
					TIM1_CH4	
					COMP1_OUT	
					SPI1_MISO/I ² S1_MCK	
					TIM1_BKIN2	
45	PA12	I/O	COM		EVENTOUT	-
					USART1_RTS	
					TIM1_ETR	
					COMP2_OUT	
					SPI1_MOSI/I ² S1_SD	
					SPI1_SCK/I ² S1_CK	
46	PA13-SWD	I/O	COM	(2)	EVENTOUT	-
					SWDIO	
					IR_OUT	
					USART1_RX	
					PVD_OUT	
47	PF5	I/O	COM		TIM1_BKIN2	RTC_OUT, COM3
48	PF6	I/O	COM		USART1_CTS	-

Packages	Reset	Port type	Port structure	Notes	Functions	
LQFP64 R1					Alternate functions	Additional functions
49	PA14-SWC	I/O	COM	(2)	EVENTOUT	-
					SWCLK	
					USART2_TX	
					USART1_TX	
					PVD_OUT	
50	PA15	I/O	COM		EVENTOUT	-
					SPI1_NSS/I ² S1_WS	
					USART2_RX	
					TIM2_CH1_ETR	
					USART4_RTS	
					USART3_RTS	
51	PC10	I/O	COM		USART4_TX	COM4/SEG39
					USART3_TX	
					TIM1_CH3	
52	PC11	I/O	COM		USART4_RX	COM5/SEG38
					USART3_RX	
					TIM1_CH4	
53	PC12	I/O	COM		USART4_CK	COM6/SEG37
					USART3_CK	
					TIM14_CH1	
54	PF7	I/O	COM		TIM3_ETR	COM7/SEG36
					USART3_RTS	
					TIM1_CH1N	
55	PB3	I/O	COM		EVENTOUT	COMP2_INN9, SEG35/VLCDH ⁽⁴⁾
					SPI1_SCK/I ² S1_CK	
					TIM2_CH2	
					USART1_RTS	
					TIM1_CH2	
56	PB4	I/O	COM		EVENTOUT	COMP1_INP12, COMP2_INP12, SEG34/VLCD3 ⁽⁴⁾
					SPI1_MISO/I ² S1_MCK	
					TIM3_CH1	
					USART1_CTS	
					USART1_CK	
					TIM1_CH2N	
					TIM17_BKIN	
57	PB5	I/O	COM		SPI1_MOSI/I ² S1_SD	COMP1_INP13,

Packages	Reset	Port type	Port structure	Notes	Functions	
LQFP64 R1					Alternate functions	Additional functions
					TIM3_CH2	SEG33/VLCD2 ⁽⁴⁾
					TIM16_BKIN	
					I ² C1_SMBA	
					USART1_CK	
					COMP2_OUT	
					USART1_RTS	
					USART1_TX	
					TIM1_CH3N	
58	PB6	I/O	COM		EVENTOUT	COMP1_INP14, COMP2_INP14, SEG32/VLCD1 ⁽⁴⁾
					USART1_TX	
					I ² C1_SCL	
					TIM16_CH1N	
					SPI2_MISO/I ² S2_MCK	
					USART3_CTS	
					TIM1_CH3	
					I ² C2_SCL	
59	PB7	I/O	COM		EVENTOUT	PVD_IN, COMP2_INP15, SEG31
					USART1_RX	
					I ² C1_SDA	
					TIM17_CH1N	
					USART4_CTS	
					SPI2_MOSI/I ² S2_SD	
					I ² C2_SDA	
					TIM1_CH1	
60	PF8/BOOT	I/O	COM	(3)	-	SEG30
61	PB8	I/O	COM		EVENTOUT	SEG29
					I ² C1_SCL	
					I ² C2_SCL	
					TIM16_CH1	
					SPI2_SCK/I ² S2_CK	
					USART1_TX	
					USART3_TX	
					TIM15_BKIN	
					TIM1_CH1N	
62	PB9	I/O	COM		EVENTOUT	SEG28
					IR_OUT	

Packages	Reset	Port type	Port structure	Notes	Functions	
LQFP64 R1					Alternate functions	Additional functions
					I ² C1_SDA	
	TIM17_CH1					
	SPI2_NSS/I ² S2_WS					
	USART1_RX					
	USART3_RX					
	I ² C2_SDA					
63	V _{SS}	G	-		Ground	
64	V _{CC}	S	-		Digital power supply	

1. Configure by option bytes to choose PF2 or NRST.
2. After reset, PA13 and PA14 are configured as SWDIO and SWCLK AF functions, the former has an internal pull-up resistor and the latter has an internal pull-down resistor activated.
3. BOOT0 defaults to digital input mode and pull-down is enable.
4. Only external resistor mode can be used at 1/6 or 1/8 duty (SEG 32 to SEG35 disabled).

3.1. Alternate functions selected through GPIOA_AFR registers for port A

Table 3-3 Port A alternate functions mapping

PortA	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PA0	-	USART2_CTS	TIM2_CH1_ETR	-	USART4_TX	-	-	COMP1_OUT	SPI2_SCK/ I ² S2_CK	-	-	-	-	-	-	-
PA1	EVENTOUT	USART2_RTS	TIM2_CH2	-	USART4_RX	TIM15_CH1N	I ² C1_SMBA	-	SPI1_SCK/ I ² S1_CK	SPI2_MOSI/ I ² S2_SD	-	-	-	-	-	-
PA2	TIM15_CH1	USART2_TX	TIM2_CH3	-	-	-	-	COMP2_OUT	SPI1_MOSI/ I ² S1_SD	SPI2_MISO/ I ² S2_MCK	-	-	-	-	-	-
PA3	TIM15_CH2	USART2_RX	TIM2_CH4	-	-	-	-	EVENTOUT	SPI2_MISO/ I ² S2_MCK	SPI2_NSS/ I ² S2_WS	-	-	-	-	-	-
PA4	SPI1_NSS/ I ² S1_WS	USART2_CK	-	-	TIM14_CH1	-	-	EVENTOUT	SPI2_MOSI/ I ² S2_SD	USART2_TX	-	-	PVD_OUT	-	-	-
PA5	SPI1_SCK/ I ² S1_CK	-	TIM2_CH1_ETR	-	-	-	-	EVENTOUT	-	-	USART3_TX	-	-	-	-	-
PA6	SPI1_MISO/ I ² S1_MCK	TIM3_CH1	TIM1_BKIN	-	USART3_CTS	TIM16_CH1	EVENTOUT	COMP1_OUT	-	-	-	-	-	-	-	-
PA7	SPI1_MOSI/ I ² S1_SD	TIM3_CH2	TIM1_CH1N	-	TIM14_CH1	TIM17_CH1	EVENTOUT	COMP2_OUT	-	-	-	-	-	-	-	-
PA8	MCO	USART1_CK	TIM1_CH1	EVENTOUT	-	-	-	-	SPI2_NSS	-	USART1_TX	-	-	-	-	-
PA9	TIM15_BKIN	USART1_TX	TIM1_CH2	-	-	-	I ² C1_SCL	EVENTOUT	SPI2_MISO/ I ² S2_MCK	MCO	-	-	-	I ² C2_SCL	-	-
PA10	TIM17_BKIN	USART1_RX	TIM1_CH3	-	-	-	I ² C1_SDA	EVENTOUT	SPI2_MOSI/ I ² S2_SD	-	-	-	-	I ² C2_SDA	-	-
PA11	EVENTOUT	USART1_CTS	TIM1_CH4	-	-	-	-	COMP1_OUT	SPI1_MISO/ I ² S1_MCK	-	-	TIM1_BKIN2	-	-	-	-
PA12	EVENTOUT	USART1_RTS	TIM1_ETR	-	-	-	-	COMP2_OUT	SPI1_MOSI/ I ² S1_SD	SPI1_SCK/ I ² S1_CK	-	-	-	-	-	-
PA13	SWDIO	IR_OUT	-	-	-	-	-	EVENTOUT	-	USART1_RX	-	-	PVD_OUT	-	-	-
PA14	SWCLK	USART2_TX	-	-	-	-	-	EVENTOUT	-	USART1_TX	-	-	PVD_OUT	-	-	-
PA15	SPI1_NSS/ I ² S1_WS	USART2_RX	TIM2_CH1_ETR	EVENTOUT	USART4_RTS	-	-	EVENTOUT	-	-	USART3_RTS	-	-	-	-	-

3.2. Alternate functions selected through GPIOB_AFR registers for port B

Table 3-4 Port B alternate function mapping

PortB	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PB0	EVENTOUT	TIM3_CH3	TIM1_CH2N	-	USART3_CK	-	-	COMP1_OUT	SPI1_NSS/ I ² S1_WS	-	USART3_RX	-	-	-	-	-
PB1	TIM14_CH1	TIM3_CH4	TIM1_CH3N	-	USART3_RTS	-	-	EVENTOUT	-	-	-	-	-	-	-	-
PB2	-	-	-	-	-	-	-	EVENTOUT	SPI2_MISO/I ² S2_MCK	-	USART3_TX	-	-	-	-	-
PB3	SPI1_SCK/ I ² S1_CK	EVENTOUT	TIM2_CH2	-	USART1_RTS	-	-	EVENTOUT	-	-	-	TIM1_CH2	-	-	-	-
PB4	SPI1_MISO/ I ² S1_MCK	TIM3_CH1	EVENTOUT	-	USART1_CTS	TIM17_BKIN	-	-	-	-	-	TIM1_CH2N	-	USART1_CK	-	-
PB5	SPI1_MOSI/ I ² S1_SD	TIM3_CH2	TIM16_BKIN	I ² C1_SMBA	USART1_CK	-	-	COMP2_OUT	-	USART1_RTS	-	TIM1_CH3N	-	USART1_TX	-	-
PB6	USART1_TX	I ² C1_SCL	TIM16_CH1N	-	-	-	-	EVENTOUT	SPI2_MISO/I ² S2_MCK	-	USART3_CTS	TIM1_CH3	-	I ² C2_SCL	-	-
PB7	USART1_RX	I ² C1_SDA	TIM17_CH1N	-	USART4_CTS	-	-	EVENTOUT	SPI2_MOSI/I ² S2_SD	-	-	TIM1_CH1	-	I ² C2_SDA	-	-
PB8	-	I ² C1_SCL	TIM16_CH1	-	-	-	-	EVENTOUT	SPI2_SCK/I ² S2_CK	USART1_TX	USART3_TX	TIM15_BKIN	-	I ² C2_SCL	TIM1_CH1N	-
PB9	IR_OUT	I ² C1_SDA	TIM17_CH1	EVENTOUT	-	SPI2_NSS/ I ² S2_WS	-	-	-	USART1_RX	USART3_RX	-	-	I ² C2_SDA	-	-
PB10	-	I ² C2_SCL	TIM2_CH3	-	USART3_TX	SPI2_SCK/ I ² S2_CK	-	COMP1_OUT	-	USART2_RTS	-	-	-	I ² C1_SCL	-	-
PB11	EVENTOUT	I ² C2_SDA	TIM2_CH4	-	USART3_RX	-	-	COMP2_OUT	SPI2_MOSI/I ² S2_SD	USART2_CTS	-	-	-	I ² C1_SDA	-	-
PB12	SPI2_NSS/ I ² S2_WS	EVENTOUT	TIM1_BKIN	-	USART3_CK	TIM15_BKIN	-	-	-	-	-	-	-	-	-	-
PB13	SPI2_SCK/ I ² S2_CK	-	TIM1_CH1N	-	USART3_CTS	I ² C2_SCL	-	EVENTOUT	-	MCO	-	TIM15_CH1N	-	I ² C1_SCL	-	-
PB14	SPI2_MISO/ I ² S2_MCK	TIM15_CH1	TIM1_CH2N	-	USART3_RTS	I ² C2_SDA	-	EVENTOUT	-	-	-	-	-	I ² C1_SDA	-	-
PB15	SPI2_MOSI/ I ² S2_SD	TIM15_CH2	TIM1_CH3N	TIM15_CH1N	-	-	-	EVENTOUT	-	-	-	-	-	-	-	-

3.3. Alternate functions selected through GPIOC_AFR registers for port C

Table 3-5 Port C alternate function mapping

PortC	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PC0	EVENTOUT	-	-	-	-	-	-	-	SPI1_MISO/I ² S1_MCK	USART2_CTS	USART3_RTS	-	-	-	-	-
PC1	EVENTOUT	-	-	-	-	-	-	-	SPI1_MOSI/I ² S1_SD	USART2_RTS	USART3_CTS	TIM15_CH1	-	-	-	-
PC2	EVENTOUT	SPI2_MISO/I ² S2_MCK	-	-	-	-	-	-	-	USART3_TX	USART3_RX	TIM15_CH2	-	-	-	-
PC3	EVENTOUT	SPI2_MOSI/I ² S2_SD	-	-	-	-	-	-	-	USART3_RX	USART3_TX	-	-	-	-	-
PC4	EVENTOUT	USART3_TX	-	-	-	-	-	-	SPI1_NSS/I ² S1_WS	USART1_TX	-	TIM2_CH1_ETR	IR_OUT	-	-	-
PC5	-	USART3_RX	-	-	-	-	-	-	SPI1_MOSI/I ² S1_SD	USART1_RX	-	TIM2_CH2	-	-	-	-
PC6	TIM3_CH1	-	-	-	-	-	-	-	SPI2_SCK/I ² S2_CK	-	USART4_RX	TIM2_CH3	-	-	-	-
PC7	TIM3_CH2	-	-	-	-	-	-	-	SPI2_MISO/I ² S2_MCK	-	USART4_TX	TIM2_CH4	-	-	-	-
PC8	TIM3_CH3	-	-	-	-	-	-	-	SPI2_MOSI/I ² S2_SD	-	USART4_CTS	TIM1_CH1	-	-	-	-
PC9	TIM3_CH4	-	-	-	-	-	-	-	SPI2_NSS/I ² S2_WS	SPI1_SCK/ I ² S1_CK	USART4_RTS	TIM1_CH2	-	-	-	-
PC10	USART4_TX	USART3_TX	-	-	-	-	-	-	-	-	-	TIM1_CH3	-	-	-	-
PC11	USART4_RX	USART3_RX	-	-	-	-	-	-	-	-	-	TIM1_CH4	-	-	-	-
PC12	USART4_CK	USART3_CK	-	-	-	-	-	-	-	-	-	TIM14_CH1	-	-	-	-
PC13	-	-	-	-	-	-	-	-	SPI1_SCK/I ² S1_CK	-	-	TIM1_BKIN	-	-	-	-
PC14	-	-	-	-	-	-	-	-	-	-	-	TIM1_BKIN2	-	-	-	-
PC15	-	-	-	-	-	-	-	-	-	-	-	TIM15_BKIN	-	-	-	-

3.4. Alternate functions selected through GPIOF_AFR registers for port F

Table 3-7 Port F alternate function mapping

PortF	AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7	AF8	AF9	AF10	AF11	AF12	AF13	AF14	AF15
PF0	-	-	-	-	-	-	-	-	-	USART2_TX	-	TIM14_CH1	-	TIM1_BKIN	-	-
PF1	-	-	-	-	-	-	-	-	-	USART2_RX	-	TIM15_CH1N	-	TIM1_CH1N	-	-
PF2	EVENTOUT	-	-	-	-	-	-	-	MCO	-	-	-	-	TIM1_CH2	-	-
PF3	EVENTOUT	-	-	-	-	-	I ² C1_SCL	-	-	-	-	-	-	I ² C2_SCL	-	-
PF4	-	-	-	-	-	-	I ² C1_SDA	-	-	-	-	-	-	I ² C2_SDA	-	-
PF5	-	-	TIM1_BKIN2	-	-	-	-	-	-	-	-	-	-	-	-	-
PF6	-	-	-	-	USART1_CTS	-	-	-	-	-	-	-	-	-	-	-
PF7	TIM3_ETR	USART3_RTS	-	-	-	-	-	-	-	-	-	TIM1_CH1N	-	-	-	-
PF8	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
PF9	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

4. Memory mapping

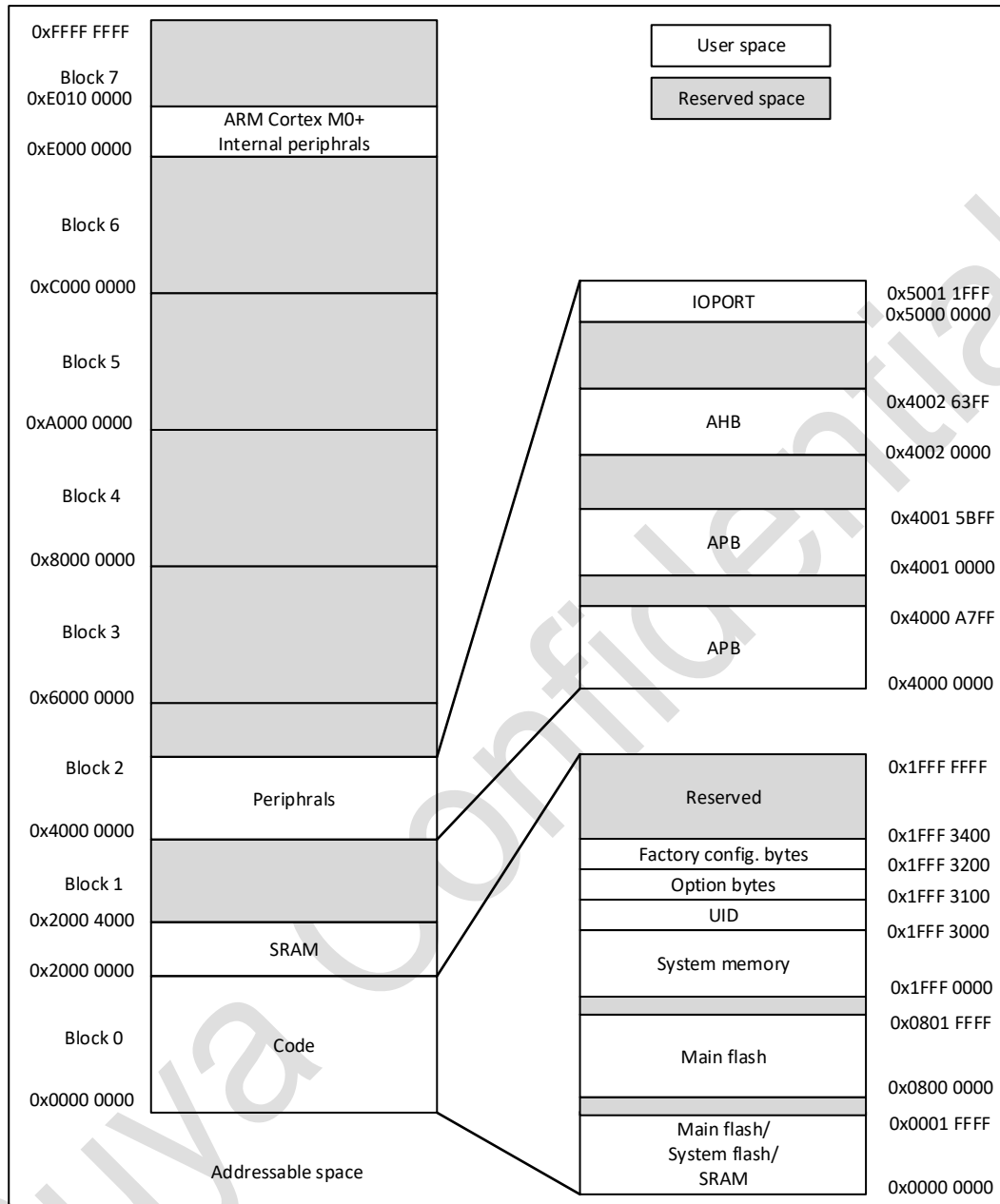


Figure 4-1 Memory mapping

Table 4-1 Memory boundary address

Type	Boundary address	Size	Memory area	Description
SRAM	0x2000 4000-0x3FFF FFFF	-	Reserved ⁽¹⁾	-
	0x2000 0000-0x2000 3FFF	16 KB	SRAM	Up to 16 KB SRAM
Code	0x1FFF 3400-0x1FFF FFFF	-	Reserved	-
	0x1FFF 3300-0x1FFF 33FF	256 Bytes	Factory config.bytes 1	Store trimming data (including HSI trimming) and power-on verification code reading
	0x1FFF 3200-0x1FFF 32FF	256 Bytes	Factory config.bytes 0	HSI trimming data, Flash erase/write time configuration parameters
	0x1FFF 3100-0x1FFF 31FF	256 Bytes	Option bytes	Option bytes information
	0x1FFF 3000-0x1FFF 30FF	256 Bytes	UID bytes	Unique ID
	0x1FFF 0000-0x1FFF 2FFF	12 KB	System memory	Boot loader
	0x0802 0000-0x1FFE FFFF	-	Reserved	-
	0x0800 0000-0x0801 FFFF	128 KB	Main flash memory	-
	0x0002 0000-0x07FF FFFF	-	Reserved	-
	0x0000 0000-0x0001 FFFF	128 KB	Selected based on Boot configuration: 1.Main flash memory 2.System memory 3.SRAM	-

1. The address is marked as Reserved , which cannot be written , read as 0 , and a response error is generated .

Table 4-2 Peripheral register boundary address⁽¹⁾

Bus	Boundary address	Size	Peripherals
	0xE000 000 - 0xE00F FFFF	1 MB	M0+
IOPORT	0x5000 1800 - 0x5FFF FFFF	-	Reserved
	0x5000 1400 - 0x5000 17FF	1 KB	GPIOF
	0x5000 0C00 - 0x5000 13FF	1 KB	Reserved
	0x5000 0800 - 0x5000 0BFF	1 KB	GPIOC
	0x5000 0400 - 0x5000 07FF	1 KB	GPIOB
	0x5000 0000 - 0x5000 03FF	1 KB	GPIOA
AHB	0x4002 3C00 - 0x4FFF FFFF	-	Reserved
	0x4002 3800 - 0x4002 3BFF	1 KB	DIV
	0x4002 3400 - 0x4002 37FF	1 KB	Reserved
	0x4002 3000 - 0x4002 33FF	1 KB	CRC
	0x4002 2400 - 0x4002 2FFF	-	Reserved
	0x4002 2000 - 0x4002 23FF	1 KB	Flash
	0x4002 1C00 - 0x4002 1FFF	-	Reserved
	0x4002 1800 - 0x4002 1BFF	1 KB	EXTI
	0x4002 1400 - 0x4002 17FF	-	Reserved
	0x4002 1000 - 0x4002 13FF	1 KB	RCC ⁽²⁾
	0x4002 0400 - 0x4002 0FFF	-	Reserved
	0x4002 0000 - 0x4002 03FF	1 KB	DMA
APB	0x4001 5C00 - 0x4001 FFFF	-	Reserved

Bus	Boundary address	Size	Peripherals
	0x4001 5800 - 0x4001 5BFF	1 KB	DBG
	0x4001 4C00 - 0x4001 57FF	-	Reserved
	0x4001 4800 - 0x4001 4BFF	1 KB	TIM17
	0x4001 4400 - 0x4001 47FF	1 KB	TIM16
	0x4001 4000 - 0x4001 43FF	1 KB	TIM15
	0x4001 3C00 - 0x4001 3FFF	-	Reserved
	0x4001 3800 - 0x4001 3BFF	1 KB	USART1
	0x4001 3400 - 0x4001 37FF	-	Reserved
	0x4001 3000 - 0x4001 33FF	1 KB	SPI1/I2S1
	0x4001 2C00 - 0x4001 2FFF	1 KB	TIM1
	0x4001 2800 - 0x4001 2BFF	-	Reserved
	0x4001 2400 - 0x4001 27FF	1 KB	ADC
	0x4001 0400 - 0x4001 23FF	-	Reserved
	0x4001 0300 - 0x4001 03FF	1 KB	OPA
	0x4001 0200 - 0x4001 02FF		COMP
	0x4001 0000 - 0x4001 01FF		SYSCFG
	0x4000 8000 - 0x4000 FFFF	-	Reserved
	0x4000 7C00 - 0x4000 7FFF	1 KB	LPTIM1
	0x4000 7400 - 0x4000 7BFF	-	Reserved
	0x4000 7000 - 0x4000 73FF	1 KB	PWR ⁽³⁾
	0x4000 5C00 - 0x4000 6FFF	-	Reserved
	0x4000 5800 - 0x4000 5BFF	1 KB	I ² C2
	0x4000 5400 - 0x4000 57FF	1 KB	I ² C1
	0x4000 5000 - 0x4000 53FF	-	Reserved
	0x4000 4C00 - 0x4000 4FFF	1 KB	USART4
	0x4000 4800 - 0x4000 4BFF	1 KB	USART3
	0x4000 4400 - 0x4000 47FF	1 KB	USART2
	0x4000 3C00 - 0x4000 43FF	-	Reserved
	0x4000 3800 - 0x4000 3BFF	1 KB	SPI2/I2S2
	0x4000 3400 - 0x4000 37FF	1 KB	Reserved
	0x4000 3000 - 0x4000 33FF	1 KB	IWDG
	0x4000 2C00 - 0x4000 2FFF	1 KB	WWDG
	0x4000 2800 - 0x4000 2BFF	1 KB	RTC
	0x4000 2400 - 0x4000 27FF	1 KB	LCD
	0x4000 2000 - 0x4000 23FF	1 KB	TIM14
	0x4000 1800 - 0x4000 1FFF	-	Reserved
	0x4000 1400 - 0x4000 17FF	1 KB	TIM7
	0x4000 1000 - 0x4000 13FF	1 KB	TIM6
	0x4000 0800 - 0x4000 0FFF	-	Reserved
	0x4000 0400 - 0x4000 07FF	1 KB	TIM3

Bus	Boundary address	Size	Peripherals
	0x4000 0000 - 0x4000 03FF	1 KB	TIM2

1. In the above table, the reserved address cannot be written, read back is 0, and a HardFault is generated
2. Not only supports 32 bits word access, but also supports halfword and byte access.
3. Not only supports 32 bits word access, but also supports halfword access.

5. Electrical characteristics

5.1. Parameter conditions

Unless otherwise specified, all voltages are referenced to V_{SS} .

5.1.1. Minimum and maximum values

Unless otherwise specified, the minimum and maximum values are guaranteed in the worst conditions of ambient temperature, supply voltage and frequencies by tests in production on 100% of the devices with an ambient temperature at $T_A = 25\text{ }^{\circ}\text{C}$ and $T_A = T_{A(\text{max})}$ (given by the selected temperature range).

Data based on electrical characterization results, design simulations and/or technology characteristics are indicated in the table footnotes and are not tested in production. Based on characterization, the minimum and maximum values refer to sample tests and represent the mean value plus or minus three times the standard deviation.

5.1.2. Typical values

Unless otherwise specified, typical data are based on $T_A = 25\text{ }^{\circ}\text{C}$ and $V_{CC} = 3.3\text{ V}$. They are given only as design guidelines and are not tested.

Typical ADC accuracy values are determined by characterization of a batch of samples from a standard diffusion lot over the full temperature range, where 95 % of the devices have an error less than or equal to the value indicated.

5.1.3. Power supply scheme

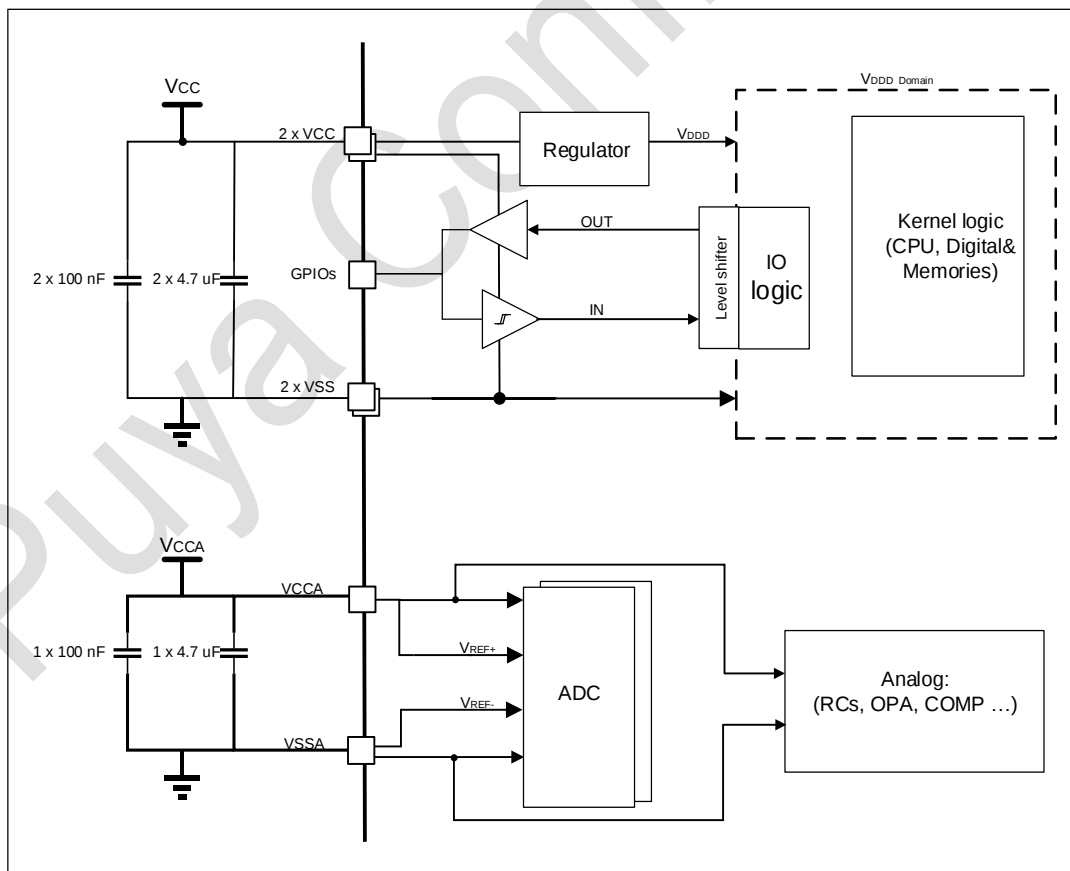


Figure 5-1 Power supply scheme

5.2. Absolute maximum ratings

Stresses above the absolute maximum ratings listed in following tables may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 5-1 Voltage characteristics ⁽¹⁾

Symbol	Ratings	Min	Max	Unit
$V_{CC}-V_{SS}$	External mains power supply	-0.3	6.25	V
V_{IN}	Input voltage of other pins	-0.3	$V_{CC}+0.3$	V

1. All main power (V_{CC} , V_{CCA}) and ground (V_{SS} , V_{SSA}) pins must always be connected to the external power supply, in the permitted range.

Table 5-2 Current characteristics

Symbol ⁽²⁾	Ratings	Max	Unit
ΣI_{VCC}	Total current into sum of all V_{CC} power lines (source) ⁽¹⁾	170	mA
ΣI_{VSS}	Total current out of sum of all V_{SS} ground lines (sink) ⁽¹⁾	170	mA
$I_{IO(PIN)}^{(2)}$	Output current sunk by any I/O and control pin	20	mA
	Output current source by any I/Os and control pin	20	
$\Sigma I_{IO(PIN)}^{(2)}$	Total output current sunk by sum of all I/Os and control pins	150	mA
	Total output current sourced by sum of all I/Os and control pins	150	

1. Power supply V_{CC} and ground V_{SS} pins must always be connected to the external power supply within the allowable range.
2. These I/O types refer to the terms and symbols defined by pins.

Table 5-3 Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
T_{STG}	Storage temperature range	-	-65 to +150	°C
T_O	Operating temperature range	-	-40 to +105	°C

5.3. Operating conditions

5.3.1. General operating conditions

Table 5-4 General operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
f_{HCLK}	Internal AHB clock frequency	-	0	24	MHz
f_{PCLK}	Internal APB Clock frequency	-	0	24	MHz
V_{CC}	Standard operating voltage	-	1.7	5.5	V
V_{CCA}	Operating voltage of analog circuit	Must be the same as V_{CC}	1.7	5.5	V
V_{IN}	I/O input voltage	-	-0.3	$V_{CC}+0.3$	V
T_A	Ambient temperature	-	-40	105	°C
T_J	Junction temperature	-	-40	110	°C

5.3.2. Operating conditions at power-up/power-down

Table 5-5 Operating conditions at power-up / power-down

Symbol	Parameter	Conditions	Min	Max	Unit
t_{VCC}	V_{CC} rise time rate	-	0	∞	$\mu s/V$
	V_{CC} fall time rate	-	20	∞	

5.3.3. Embedded reset and PVD module characteristics

Table 5-6 POR/PDR/BOR module characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t _{RSTTEMPO} ⁽¹⁾	Reset temporization	-	-	4.0	7.5	ms
V _{POR/PDR}	Power-on/power-down reset threshold	Rising edge	1.5	1.6	1.7	V
		Falling edge	1.45	1.55	1.65	
V _{PDRhyst} ⁽¹⁾	PDR hysteresis	-	-	50	-	mV
V _{BOR}	BOR threshold	BOR_LEV[2:0]=111 (Rising edge)	3.1	3.2	3.3	V
		BOR_LEV[2:0]=111 (Falling edge)	3	3.1	3.2	
		Others	Reserved			
V _{BOR_hyst}	BOR hysteresis	-	-	100	-	mV

1. Guaranteed by design, not tested in production.

Table 5-7 PVD module characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{PVD} ⁽²⁾	PVD threshold	PLS[2:0]=111 (Rising edge)	3.1	3.2	3.3	V
		PLS[2:0]=111 (Falling edge)	3	3.1	3.2	
		Others	Reserved			
V _{PVDhyst} ⁽¹⁾	PVD hysteresis	-	-	100	-	mV

1. Guaranteed by design, not tested in production.

2. Data based on characterization results, not tested in production

5.3.4. Supply current characteristics

Table 5-8 Current consumption in Run mode

Symbol	Conditions						Typ ⁽¹⁾	Max ⁽¹⁾		Unit	
	System clock	Frequency	Code	Run	Peripheral clock	Flash sleep		T _A = 85 °C	T _A = 105 °C		
I _{cc} (Run)	HSI	24 MHz	While(1)	Flash	ON	DISABLE	3.8	4.3	5.3	mA	
					OFF	DISABLE	2.6	2.8	3.8		
		8 MHz			ON	DISABLE	1.8	2.5	3.1		
					OFF	DISABLE	1.2	2.3	3.0		
	LSI	32.768 kHz			ON	DISABLE	350	609.7	1116.7	μA	
					OFF	DISABLE	293	484.4	860.1		
					23.552 kHz	ON	ENABLE	277	497.6		829.9
						OFF	ENABLE	225	370.8		587.2
		38.912 kHz				ON	DISABLE	297.5	518.2		949.2
						OFF	DISABLE	249.1	411.7		731.1
					39.168 kHz	ON	ENABLE	235.5	423.0		705.4
						OFF	ENABLE	191.3	315.2		499.1
		43.008 kHz				ON	DISABLE	455.0	792.6		1451.7
						OFF	DISABLE	380.9	629.7		1118.1
						ON	ENABLE	360.1	646.9		1078.9
						OFF	ENABLE	292.5	482.0		763.4
						ON	DISABLE	490.0	853.6		1563.4
						OFF	DISABLE	410.2	678.2		1204.1
						ON	ENABLE	387.8	696.6		1161.9
						OFF	ENABLE	315.0	519.1		822.1
						ON	DISABLE	525.0	914.6		1675.1
						OFF	DISABLE	439.5	726.6		1290.2
						ON	ENABLE	415.5	746.4		1244.9
						OFF	ENABLE	337.5	556.2		880.8

1. Data based on characterization results, not tested in production.

Table 5-9 Current consumption in Sleep mode

Symbol	Conditions				Typ ⁽¹⁾	Max ⁽¹⁾		Unit
	System clock	Frequency	Peripheral clock	Flash sleep		T _A =85 °C	T _A =105 °C	
I _{cc} (Sleep)	HSI	24 MHz	ON	DISABLE	2.1	2.9	3.8	mA
			OFF	DISABLE	0.9	1.2	1.7	
		8 MHz	ON	DISABLE	1.0	2.3	3.0	
			OFF	DISABLE	0.5	0.8	1.3	
	LSI	32.768 kHz	ON	DISABLE	349	620.5	1110.2	μA
			OFF	DISABLE	293	508.2	853.1	
			ON	ENABLE	278	557.1	914.6	
			OFF	ENABLE	224	446.0	655.6	
		23.552 kHz	ON	DISABLE	296.6	527.4	943.7	
			OFF	DISABLE	249.1	431.9	725.1	
			ON	ENABLE	236.3	473.5	777.4	
			OFF	ENABLE	190.4	379.1	557.3	
		38.912 kHz	ON	DISABLE	453.7	806.6	1443.3	
			OFF	DISABLE	380.9	660.7	1109.0	
			ON	ENABLE	361.4	724.2	1189.0	
			OFF	ENABLE	291.2	579.8	852.3	
		39.168 kHz	ON	DISABLE	488.6	868.7	1554.3	
			OFF	DISABLE	410.2	711.5	1194.3	
			ON	ENABLE	389.2	779.9	1280.4	
			OFF	ENABLE	313.6	624.4	917.8	
		43.008 kHz	ON	DISABLE	523.5	930.8	1665.3	
			OFF	DISABLE	439.5	762.3	1279.7	
			ON	ENABLE	417.0	835.7	1371.9	
			OFF	ENABLE	336.0	669.0	983.4	

1. Data based on characterization results, not tested in production.

Table 5-10 Current consumption in Stop mode

Symbol	Conditions					Typ ⁽¹⁾	Max		Unit
	V _{CC}	V _{DDx}	MR/LPR	LSI	Peripheral clock		T _A = 85 °C	T _A = 105 °C	
I _{cc} (Stop)	3.0 to 5.5 V	1.2 V	MR (LPR = 0)	-	-	130	356.7	519.1	μA
		1.2 V	LPR (LPR = 1)	ON	RTC + IWDG + LPTIM	9.2	212.2	330.5	
					IWDG	9.3	212.1	330.6	
					LPTIM	9.3	211.8	330.0	
					RTC	9.2	211.8	330.2	
				OFF	-	9.0	211.8	330.1	
		1.0 V		ON	RTC + IWDG + LPTIM	7.2	162.1	254.1	
					IWDG	7.3	162.1	254.0	
					LPTIM	7.3	161.8	253.7	
					RTC	7.2	161.8	253.5	
				OFF	-	7.0	161.8	253.6	
		0.9V		ON	RTC + IWDG + LPTIM	6.2	124.9	196.0	
					IWDG	6.3	124.9	196.1	
					LPTIM	6.3	124.6	195.5	
					RTC	6.2	124.6	195.6	
				OFF	-	6.0	124.6	195.6	
		0.8 V		ON	RTC + IWDG + LPTIM	5.2	110.8	233.9	
					IWDG	5.3	112.5	248.1	
					LPTIM	5.3	110.6	238.2	
					RTC	5.2	112.0	266.8	
				OFF	-	5.0	110.1	267.2	

1. Data based on characterization results, not tested in production.

5.3.5. Wake-up time from low-power mode

Table 5-11 Low-power mode wake-up timings

Symbol	Parameter ⁽¹⁾	Conditions		Typ ⁽²⁾	Max	Unit
$t_{WUSLEEP}$	Wake-up from Sleep mode to Run mode in Flash	-		7	-	CPU cycles
t_{WUSTOP}	Wake-up from Stop mode o Run mode in Flash	Regulator in MR mode (LPR = 0)	HSI (24 MHz) as system clock	3	-	μs
			HSI (8 MHz) as system clock	4.5	-	
		Regulator in LPR mode (LPR = 1)	HSI (24 MHz) as system clock	6	-	
			HSI (8 MHz) as system clock	7	-	

- The wake-up time is measured from the wake-up time until the first instruction is read by the user program.
- Data based on characterization results, not tested in production.

5.3.6. External clock source characteristics

5.3.6.1. High-speed external clock generated from an external source

In bypass mode of HSE (the HSEBYP of RCC_CR is set), when the high-speed start-up circuit in the chip stops working, the corresponding I/O is used as a standard GPIO.

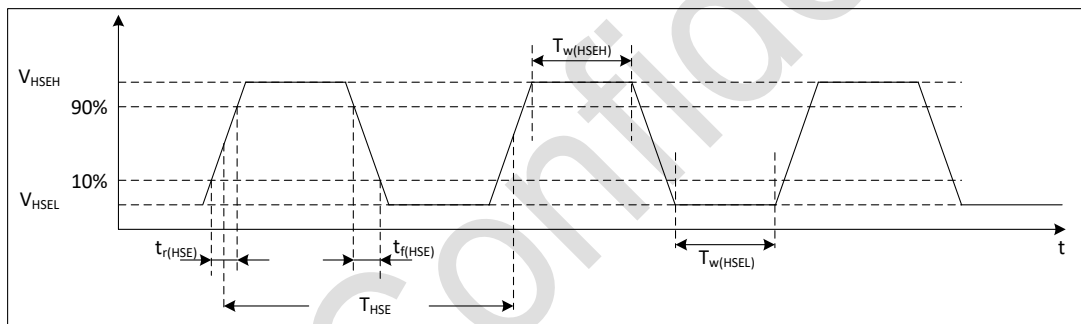


Figure 5-2 High-speed external clock timing diagram

Table 5-12 High-speed external clock characteristics

Symbol	Parameter ⁽¹⁾	Min	Typ	Max	Unit
f_{HSE_ext}	User external clock source frequency	1	8	24	MHz
V_{HSEH}	Input pin high level voltage	$0.7V_{CC}$	-	V_{CC}	V
V_{HSEL}	Input pin low level voltage	V_{SS}	-	$0.3V_{CC}$	
$t_{W(HSEH)}$ $t_{W(HSEL)}$	High or low time	15	-	-	ns
$t_{r(HSE)}$ $t_{f(HSE)}$	Rise or fall time	-	-	20	ns

- Guaranteed by design, not tested in production.

5.3.6.2. Low-speed external clock generated from an external source

In the bypass mode of LSE (the LSE BYP of RCC_BDCR is set), the low-speed start-up circuit in the chip stops working, and the corresponding I/O is used as a standard GPIO.

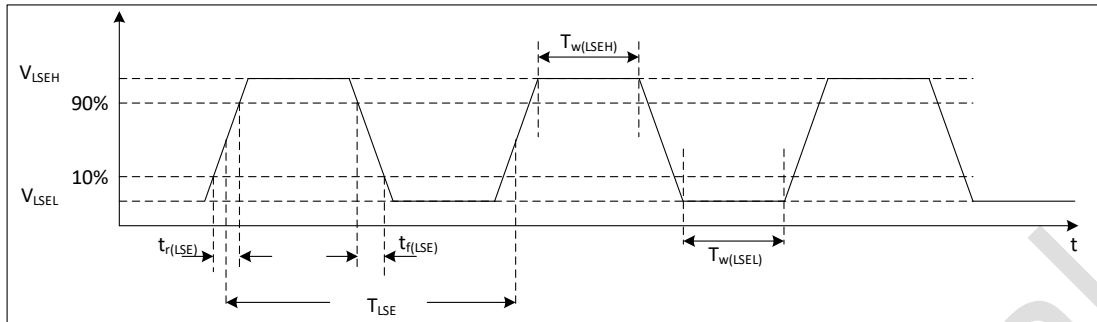


Figure 5-3 Low-speed external clock timing diagram

Table 5-13 Low-speed external clock characteristics

Symbol	Parameter ⁽¹⁾	Min	Typ	Max	Unit
f_{LSE_ext}	User external clock frequency	-	32.768	1000	kHz
V_{LSEH}	Input pin high level voltage	$0.7V_{CC}$	-	-	V
V_{LSEL}	Input pin low level voltage	-	-	$0.3V_{CC}$	V
$t_{W(LSEH)}$ $t_{W(LSEL)}$	High or low time	450	-	-	ns
$t_{r(LSE)}$ $t_{f(LSE)}$	Rise or fall time	-	-	50	ns

1. Guaranteed by design, not tested in production.

5.3.6.3. High-speed external clock generated from a crystal/ceramic resonator

The high-speed external (HSE) clock can be supplied with 4 to 24 MHz crystal/ceramic resonator oscillator. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time.

Table 5-14 HSE oscillator characteristics

Symbol	Parameter	Conditions ⁽¹⁾	Min ⁽²⁾	Typ	Max ⁽²⁾	Unit
f_{OSC_IN}	Oscillator frequency	-	4	-	24	MHz
R_F	Feedback resistor	-	-	200	-	k Ω
$I_{CC}^{(4)}$	HSE current consumption	$R_m=100\ \Omega$, $C_L=12\ \text{pF}@4\ \text{MHz}$ HSE_DRV [1:0] = 01	-	0.5	-	mA
		$R_m=150\ \Omega$, $C_L=12\ \text{pF}@8\ \text{MHz}$ HSE_DRV [1:0] = 01	-	0.5	-	
		$R_m=70\ \Omega$, $C_L=12\ \text{pF}@16\ \text{MHz}$ HSE_DRV [1:0] = 10	-	1.1	-	
		$R_m=40\ \Omega$, $C_L=20\ \text{pF}@24\ \text{MHz}$ HSE_DRV [1:0] = 11	-	1.5	-	
$t_{SU(HSE)}^{(3)(4)}$	Startup time	$R_m=100\ \Omega$, $C_L=12\ \text{pF}@4\ \text{MHz}$ HSE_STARTUP [1:0] = 00 HSE_DRV [1:0] = 01	-	2.0	-	ms
		$R_m=150\ \Omega$,	-	2.5	-	

Symbol	Parameter	Conditions ⁽¹⁾	Min ⁽²⁾	Typ	Max ⁽²⁾	Unit
		C _L =12 pF@8 MHz HSE_STARTUP [1:0] = 00 HSE_DRV [1:0] = 01				
		R _m =70 Ω, C _L =12 pF@16 MHz HSE_STARTUP [1:0] = 00 HSE_DRV [1:0] = 10	-	2.5	-	
		R _m =40 Ω, C _L =20 pF@24 MHz HSE_STARTUP [1:0] = 00 HSE_DRV [1:0] = 11	-	0.6	-	

- Crystal/ceramic resonator characteristics are based on the manufacturer's datasheet.
- Guaranteed by design, not tested in production.
- t_{SU(HSE)} is the startup time from enable (by software) to when the clock oscillation reaches a stable state , measured for a standard crystal/resonator, which can vary considerably from one crystal/resonator to another .
- Data based on characterization results, not tested in production.

5.3.6.4. Low-speed external clock generated from a crystal resonator

The low-speed external (LSE) clock can be supplied with a 32.768 kHz crystal resonator oscillator. In the application, the resonator and the load capacitors have to be placed as close as possible to the oscillator pins in order to minimize output distortion and startup stabilization time.

Table 5-15 LSE oscillator characteristics

Symbol	Parameter	Conditions ⁽¹⁾	Min ⁽²⁾	Typ	Max ⁽²⁾	Unit
I _{CC} ⁽⁴⁾	LSE current consumption	C _L =6 pF@32.768 kHz LSE_DRIVER [1:0] = 01	-	0.7	-	μA
		C _L =12 pF@32.768 kHz LSE_DRIVER [1:0] = 10	-	1.1	-	
		C _L =12 pF@32.768 kHz LSE_DRIVER [1:0] = 11	-	1.5	-	
t _{SU(LSE)} ⁽³⁾⁽⁴⁾	Startup time	C _L =6 pF@32.768 kHz LSE_DRIVER [1:0] = 01	-	0.6	-	s
		C _L =12 pF@32.768 kHz LSE_DRIVER [1:0] = 10	-	0.9	-	
		C _L =12 pF@32.768 kHz LSE_DRIVER [1:0] = 11	-	0.6	-	

- Crystal/ceramic resonator characteristics are based on the manufacturer's datasheet.
- Guaranteed by design, not tested in production.
- t_{SU(LSE)} is the startup time from enable (by software) to when the clock oscillation reaches a stable , measured for a standard crystal/resonator , which may vary greatly from crystal to resonator.
- Data based on characterization results, not tested in production.

5.3.7. High-speed internal (HSI) RC oscillator

Table 5-16 HSI8 MHz oscillator characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f _{HSI}	HSI frequency	-	-	8.0	-	MHz
ΔTemp(HSI)	HSI frequency drift over temperature	V _{CC} = 3.0 to 5.5 V, T _A = -20 to 85 °C	-2 ⁽²⁾	-	2 ⁽²⁾	%
		V _{CC} = 3.0 to 5.5 V, T _A = -40 to 105 °C	-4 ⁽²⁾	-	4 ⁽²⁾	
D _{HSI} ⁽¹⁾	Duty cycle	-	45 ⁽¹⁾	-	55 ⁽¹⁾	%
t _{Stab} (HSI)	HSI stabilization time	-	-	2	4 ⁽¹⁾	μs
I _{CC} (HSI) ⁽²⁾	HSI power consumption	8 MHz	-	120	-	μA

- Guaranteed by design, not tested in production.
- Data based on characterization results, not tested in production.

Table 5-17 HSI24 MHz oscillator characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{HSI}	HSI frequency	-	-	24.0	-	MHz
$\Delta T_{\text{emp(HSI)}}$	HSI frequency drift over temperature	$V_{\text{CC}} = 3.0 \text{ to } 5.5 \text{ V}, T_{\text{A}} = -20 \text{ to } 85 \text{ }^{\circ}\text{C}$	-1 ⁽²⁾	-	1 ⁽²⁾	%
		$V_{\text{CC}} = 3.0 \text{ to } 5.5 \text{ V}, T_{\text{A}} = -40 \text{ to } 105 \text{ }^{\circ}\text{C}$	-3 ⁽²⁾	-	3 ⁽²⁾	
$D_{\text{HSI}}^{(1)}$	Duty cycle	-	45 ⁽¹⁾	-	55 ⁽¹⁾	%
$t_{\text{stab(HSI)}}$	HSI stabilization time	-	-	2	4 ⁽¹⁾	μs
$I_{\text{CC(HSI)}}^{(2)}$	HSI power consumption	24 MHz	-	210	-	μA

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.

5.3.8. Low-speed internal (LSI) RC oscillator

Table 5-18 LSI oscillator characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{LSI}	LSI frequency	$T_{\text{A}} = 25 \text{ }^{\circ}\text{C}, V_{\text{CC}} = 3.3 \text{ V}$	31.78	32.768	33.75	kHz
			22.85	23.552	24.26	
			37.74	38.912	40.08	
			37.99	39.168	40.34	
			41.72	43.008	44.30	
$\Delta T_{\text{emp(LSI)}}$	LSI frequency drift over temperature	$V_{\text{CC}} = 3.3 \text{ V}, T_{\text{A}} = 25 \text{ }^{\circ}\text{C}$	-3	-	+3	%
		$V_{\text{CC}} = 3.0 \text{ to } 5.5 \text{ V}, T_{\text{A}} = 0 \text{ to } 85 \text{ }^{\circ}\text{C}$	-10 ⁽²⁾	-	10 ⁽²⁾	
		$V_{\text{CC}} = 3.0 \text{ to } 5.5 \text{ V}, T_{\text{A}} = 0 \text{ to } 105 \text{ }^{\circ}\text{C}$	-15 ⁽²⁾	-	15 ⁽²⁾	
		$V_{\text{CC}} = 3.0 \text{ to } 5.5 \text{ V}, T_{\text{A}} = -40 \text{ to } 105 \text{ }^{\circ}\text{C}$	-20 ⁽²⁾	-	20 ⁽²⁾	
$t_{\text{stab(LSI)}}^{(1)}$	LSI stabilization time	-	-	150	-	μs
$I_{\text{CC(LSI)}}^{(1)}$	LSI power consumption	-	-	300	-	nA

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.

5.3.9. Memory characteristics

Table 5-19 Memory characteristics

Symbol	Parameter	Conditions	Typ	Max ⁽¹⁾	Unit
t_{prog}	Page programming time	-	1.0	1.5	ms
t_{ERASE}	Page/sector/mass erase time	-	3.0	4.5	ms
I_{CC}	Page programming supply current	-	2.1	2.9	mA
	Page/sector/mass erase supply current	-	2.1	2.9	mA

1. Data based on characterization results, not tested in production.

Table 5-20 Memory endurance and data retention

Symbol	Parameter	Conditions	Min ⁽¹⁾	Unit
N_{END}	Endurance	$T_{\text{A}} = -40 \text{ to } 85 \text{ }^{\circ}\text{C}$	100	kcycle
		$T_{\text{A}} = 85 \text{ to } 105 \text{ }^{\circ}\text{C}$	10	
t_{RET}	Data retention	10 kcycle $T_{\text{A}} = 55 \text{ }^{\circ}\text{C}$	20	Year

1. Data based on characterization results, not tested in production.

5.3.10. EFT characteristics

Table 5-21 EFT characteristics⁽¹⁾

Symbol	Parameter	Conditions	Level/Class
EFT to power	-	IEC61000-4-4	4A

1. Data based on characterization results, not tested in production.

5.3.11. ESD & LU characteristics

Table 5-22 ESD & LU characteristics⁽¹⁾

Symbol	Parameter	Conditions	Typ	Unit
V _{ESD(HBM)}	Electrostatic discharge voltage(human body model)	ESDA/JEDEC JS-001-2017	6	kV
V _{ESD(CDM)}	Electrostatic discharge voltage (charge device model)	ESDA/JEDEC JS-002-2018	1	kV
LU	Static latch-up	JESD78E	200	mA

1. Data based on characterization results, not tested in production.

5.3.12. Port characteristics

Table 5-23 Port static characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{IH}	High level input voltage	V _{CC} = 3.0 to 5.5 V	0.7V _{CC}	-	-	V
V _{IL}	Low level input voltage	V _{CC} = 3.0 to 5.5 V	-	-	0.3V _{CC}	V
V _{hys} ⁽¹⁾	Schmitt trigger hysteresis	-	-	200	-	mV
I _{lkg}	Input leakage current	-	-	-	1	μA
R _{PU}	Weak pull-up equivalent resistor	-	30	50	70	kΩ
R _{PD}	Weak pull-down equivalent resistor	-	30	50	70	kΩ
C _{IO} ⁽¹⁾	Pin capacitance	-	-	5	-	pF
t _{ns(EXTI)} ⁽¹⁾	Input filter width	ENI=1, ENS=1	3	5	10	ns
t _{ns(I2C)} ⁽¹⁾	I ² C Input filter width	ENI=1, EIIC=1	50	140	250	ns

1. Guaranteed by design, not tested in production.

Table 5-24 Output voltage characteristics⁽³⁾

Symbol	Parameters ⁽¹⁾	Conditions		Min	Max	Unit
V _{OL} ⁽²⁾	Output low level voltage for an I/O pin	GPIOx_OSPEEDR=11	I _{OL} = 8 mA, V _{CC} ≥ 2.7 V	-	0.4	V
			I _{OL} = 4 mA, V _{CC} = 1.8 V	-	0.5	
V _{OH} ⁽²⁾	Output high level voltage for an I/O pin	GPIOx_OSPEEDR=11	I _{OH} = 8 mA, V _{CC} ≥ 2.7 V	V _{CC} - 0.4	-	V
			I _{OH} = 4 mA, V _{CC} = 1.8 V	V _{CC} - 0.5	-	

- IO types can refer to the terms and symbols defined by the pins.
- Data based on characterization results, not tested in production.
- The I_{IO} current sourced or sunk by the device must always respect the absolute maximum rating specified in [Table 5-2 Current characteristics](#), and the sum of the currents sourced or sunk by all the I/Os (I/O ports and control pins) must always respect the absolute maximum ratings ΣI_{IO(PIN)}.

5.3.13. ADC characteristics

Table 5-25 ADC characteristics⁽¹⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CCA}	Analog supply voltage for ADC ON	-	1.8	-	5.5	V
V _{REF+}	Positive reference voltage	V _{REF+} = V _{CCA}	V _{CCA}			V
		V _{REF+} = V _{REFBUF}	-	1.5	-	
			-	2.048	-	
			-	2.5	-	
V _{REF-}	Negative reference voltage	-	0			V
I _{VCCA}	ADC consumption from V _{CCA}	f _s =1 Msps	-	350	-	μA
I _{VREF+}	ADC consumption from V _{REF+}	f _s =1 Msps	-	22	-	μA
C _{ADC} ⁽¹⁾	Internal sample and hold capacitors	-	-	5	8	pF
R _{AIN} ^{(1) (3)}	External input impedance	-	-	-	31	kΩ
R _{ADC} ⁽¹⁾	Sampling switch resistance	-	-	-	2.5	kΩ
f _{ADC}	ADC clock frequency	V _{CCA} =1.8 - 2.3 V	0.8	4	8 ⁽²⁾	MHz
		V _{CCA} =2.3 - 5.5 V	0.8	8	16 ⁽²⁾	
f _s	Sampling rate	V _{CCA} =1.8 - 2.3 V	0.05	-	0.5	Msps
		V _{CCA} =2.3 - 5.5 V	0.05	-	1	
t _{CAL} ⁽¹⁾	Calibration time	f _{ADC} = 16 MHz	4.375	-	7.4375	μs
			70	-	119	1/f _{ADC}
t _{samp} ⁽¹⁾	Sampling time	f _{ADC} =16 MHz V _{CCA} =1.8 - 5.5 V	0.219	-	14.97	μs
			3.5	-	239.5	1/f _{ADC}
t _{samp_int} ⁽¹⁾	Sampling time for internal channels (V _{REFINT} , T _{S_VIN} , V _{CCA} /3, OPA 1-2)	-	20	-	-	μs
t _{conv} ⁽¹⁾	Total conversion time	V _{CCA} =1.8 - 5.5 V	12	-	248	1/f _{ADC}
t _{eoC} ⁽¹⁾	Conversion end time	V _{CCA} =1.8 - 5.5 V	0.5			1/f _{ADC}

1. Guaranteed by design, not tested in production.
2. Data based on characterization results, not tested in production.
3. Equation 1: R_{AIN} max formula

$$R_{AIN} < \frac{T_s}{f_{ADC} \times C_{ADC} \times \ln(2^{N+2})} - R_{ADC}$$

The formula above (*Equation 1*) is used to determine the maximum external impedance allowed for an error below 1/4 of LSB. Here N = 12 (from 12-bit resolution).

Table 5-26 R_{AIN} max for f_{ADC}=16 MHz⁽¹⁾

Ts (cycles)	ts (μs)	R _{AIN} max (kΩ)
3.5	0.21	0.3
5.5	0.34	1.9
7.5	0.46	3.5
13.5	0.84	8.3
28.5	1.78	20.4
41.5	2.59	30.9
134.5	8.41	-

Ts (cycles)	ts (μs)	RAIN max (kΩ)
239.5	14.96	-

1. Guaranteed by design, not tested in production.

Table 5-27 ADC accuracy⁽¹⁾⁽²⁾

Symbol	Parameter	Conditions	Typ	Max	Unit
ET	Total unadjusted error	f _{ADC} = 16 MHz, V _{CCA} = 1.8 V to 5.5 V	±6.5	±10.0	LSB
EO	Offset error		±1.3	±3.0	LSB
EG	Gain error		±2.6	±5.0	LSB
DNL	Differential linearity error		±1.2	±1.5	LSB
INL	Integral linearity error		±3.5	±6.5	LSB

1. ADC DC accuracy values are measured after internal calibration.
2. Data based on characterization results, not tested in production.

5.3.14. Comparator characteristics

Table 5-28 Comparator characteristics⁽¹⁾

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V _{IN}	Input voltage range	-		0	-	V _{CCA}	V
V _{SC}	Scaler offset voltage	-		-	±5	±10	mV
I _{CCA(SCALER)}	Scaler static consumption	-		-	0.8	1	μA
t _{START_SCALER}	Scaler startup time	-		-	100	200	μs
t _{START}	Startup time	High-speed mode		-	-	5	μs
		Medium-speed mode		-	-	15	
t _D	Propagation delay	200 mV step, 100 mV over-drive	High-speed mode	-	50	150	ns
			Medium-speed mode	-	1500	2800	
		>200 mV step, 100 mV over-drive	High-speed mode	-	-	200	
			Medium-speed mode	-	-	2900	
V _{offset}	Offset error	-		-	±5	±10	mV
V _{hys}	Hysteresis voltage	No hysteresis		-	0	-	mV
		With hysteresis		-	20	-	
I _{CCA}	Consumption	Static	High-speed mode	-	250	-	μA
			Medium-speed mode	-	7	-	
		With 50 kHz and ±100 mV overdrive square signal	High-speed mode	-	250	-	
			Medium-speed mode	-	8	-	

1. Guaranteed by design, not tested in production.

5.3.15. Operational amplifier characteristics

Table 5-29 OPA characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CCA}	Analog supply voltage		2.5	-	5.5	V
V _{IN}	Input voltage	-	0	-	V _{CCA}	V
V _{OUT}	Output voltage	-	0.2	-	V _{CCA} -0.2	V
I _{LOAD}	Drive current	-	-	-	2.2	mA

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R_L	Resister load	-	5	-	-	k Ω
C_{LOAD}	Capacitive load	-	-	-	50	pF
t_{start}	Initialization time	$C_{LOAD} \leq 50$ pF, $R_{LOAD} \geq 5$ k Ω	-	-	20	μ s
V_{IO}	Input offset voltage	$C_{LOAD} \leq 50$ pF, $R_{LOAD} \geq 5$ k Ω $V_{com}=V_{CCA}/2$	-	± 6	-	mV
PM	Phase margin	$C_{LOAD} \leq 50$ pF, $R_{LOAD} \geq 5$ k Ω $V_{com}=V_{CCA}/2$	-	80	-	Deg
UGBW	Unit gain bandwidth	$C_{LOAD} \leq 50$ pF, $R_{LOAD} \geq 5$ k Ω $V_{com}=V_{CCA}/2$	-	10	-	MHz
SR	Slew rate	-	-	7	-	V/ μ s

5.3.16. Temperature sensor characteristics

Table 5-30 Temperature sensor characteristics

Symbol	Parameter	Min	Typ	Max	Unit
$T_L^{(1)}$	V_{TS} linearity with temperature	-	± 1	± 2	$^{\circ}$ C
Avg_Slope ⁽¹⁾	Average slope	2.3	2.5	2.7	mV/ $^{\circ}$ C
V_{30}	Voltage at 30 $^{\circ}$ C (± 5 $^{\circ}$ C)	0.742	0.76	0.785	V
$t_{START}^{(1)}$	Start up time entering in continuous mode	-	70	120	μ s
$t_{s_setup}^{(1)}$	ADC sampling time when reading the temperature	20	-	-	μ s

1. Guaranteed by design, not tested in production.

5.3.17. LCD controller characteristics

Table 5-31 LCD controller characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{LCD}^{(1)(3)}$	LCD supply current	External drive resistive mode	-	0.6	-	μ A
		Internal low drive resistive mode	-	4	-	
		Internal middle drive resistive mode	-	7.5	-	
		Internal high drive resistive mode	-	10	-	
$R_H^{(2)}$	Low drive resistive	-	-	1080	-	k Ω
$R_M^{(2)}$	Middle drive resistive	-	-	540	-	
$R_L^{(2)}$	High drive resistive	-	-	360	-	
V_{LCDH}	LCD adjustable highest level voltage	-	-	V_{CCA}	-	V
V_{LCD3}	LCD highest level voltage	-	-	V_{LCDH}	-	
V_{LCD2}	LCD 2/3 level voltage	-	-	2/3 V_{LCDH}	-	
V_{LCD1}	LCD 1/3 level voltage	-	-	1/3 V_{LCDH}	-	
V_{LCD0}	LCD lowest level voltage	-	-	V_{SS}	-	
$\Delta V_{LCD}^{(3)}$	LCD segment/common level voltage error	$T_A = -40$ to 105 $^{\circ}$ C	-	-	± 50	mV

1. LCD enabled with $V_{CCA}=3.3$ V, 1/4 duty, 1/3 bias, scan frequency 256 Hz, all pixels active, no LCD connected.

2. Guaranteed by design, not tested in production.

3. Data is based on assessment results and is not tested in production.

5.3.18. Embedded voltage reference characteristics

Table 5-32 Embedded internal voltage reference (V_{REFINT}) characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{REFINT}	Internal reference voltage	-	1.17	1.2	1.23	V
$t_{start_VREFINT}$	Start time of V_{REFINT}	-	-	10	15	μs
$T_{coeff_VREFINT}$	Temperature coefficient of V_{REFINT}	-	-	-	100 ⁽¹⁾	ppm/°C
I_{REFINT}	V_{REFINT} current consumption	-	-	12	20	μA

1. Guaranteed by design, not tested in production.

5.3.19. ADC voltage reference buffer characteristics

Table 5-33 ADC voltage reference buffer(V_{REFBUF})characteristics⁽¹⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{REFBUF25}$	2.5 V Internal reference voltage	$T_A=25\text{ }^{\circ}\text{C}, V_{CCA}=3.3\text{ V}$	2.48	2.5	2.53	V
$V_{REFBUF20}$	2.048 V Internal reference voltage	$T_A=25\text{ }^{\circ}\text{C}, V_{CCA}=3.3\text{ V}$	2.03	2.048	2.07	V
$V_{REFBUF15}$	1.5 V Internal reference voltage	$T_A=25\text{ }^{\circ}\text{C}, V_{CCA}=3.3\text{ V}$	1.49	1.5	1.51	V
$t_{start_VREFBUF}$	Start time of V_{REFBUF}	-	-	-	2	μs
$T_{coeff_VREF-BUF}$	Temperature coefficient of V_{REFBUF}	$T_A=-40\text{ to }105\text{ }^{\circ}\text{C}$	-	-	120	ppm/°C

1. Guaranteed by design, not tested in production.

5.3.20. Timer characteristics

Table 5-34 Timer characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
$t_{res(TIM)}$	Timer resolution time	-	1	-	$t_{TIMxCLK}$
		$f_{TIMxCLK} = 24\text{ MHz}$	41.667	-	ns
f_{EXT}	Timer external clock frequency on CH1 to CH4	-	-	$f_{TIMxCLK}/2$	MHz
		$f_{TIMxCLK} = 24\text{ MHz}$	-	24	
Res_{TIM}	Timer resolution	TIM1/3/14/15/16/17	-	16	bit
		TIM2	-	32	
$t_{COUNTER}$	16-bit counter clock period	-	1	65536	$t_{TIMxCLK}$
		$f_{TIMxCLK} = 24\text{ MHz}$	0.041667	2731	μs

Table 5-35 LPTIM characteristics (timeout period at 32.768 kHz LSI)

Prescaler	PRESC[2:0]	Min overflow	Max overflow	Unit
/1	0	0.0305	1998.848	ms
/2	1	0.0610	3997.696	
/4	2	0.1221	8001.9456	
/8	3	0.2441	15997.3376	
/16	4	0.4883	32001.2288	
/32	5	0.9766	64002.4576	
/64	6	1.9531	127998.3616	
/128	7	3.9063	256003.2768	

Table 5-36 IWDG characteristics (timeout period at 32.768 kHz LSI)

Prescaler	PR[2:0]	Min overflow	Max overflow	Unit
/4	0	0.122	499.712	ms
/8	1	0.244	999.424	

Prescaler	PR[2:0]	Min overflow	Max overflow	Unit
/16	2	0.488	1998.848	
/32	3	0.976	3997.696	
/64	4	1.952	7995.392	
/128	5	3.904	15990.784	
/256	6 or 7	7.808	31981.568	

Table 5-37 WWDG characteristics (timeout period at 24 MHz PCLK)

Prescaler	WDGTB[1:0]	Min overflow	Max overflow	Unit
1*4096	0	0.171	10.923	ms
2*4096	1	0.341	21.845	
4*4096	2	0.683	43.691	
8*4096	3	1.365	87.381	

5.3.21. Communication interfaces

5.3.21.1. I²C interface characteristics

The I²C interface meets the timing requirements of the I²C-bus specification and user manual:

- Standard-mode (Sm): up to 100 kbit/s
- Fast-mode (Fm): up to 400 kbit/s

I²C SDA and SCL pins have analogue filtering, see table below.

Table 5-38 I²C filter characteristics

Symbol	Parameter	Min	Max	Unit
t _{AF}	Maximum width of spikes that are suppressed by the analog filter	50	260	ns

5.3.21.2. SPI characteristics

Table 5-39 SPI characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
f _{SCK} 1/t _{c(SCK)}	SPI clock frequency	Master mode	-	12	MHz
		Slave mode	-	6	
t _{r(SCK)} t _{f(SCK)}	SPI clock rise and fall time	Capacitive load: C = 15 pF	-	6	ns
t _{su(NSS)}	NSS setup time	Slave mode	2 T _{pclk}	-	ns
t _{h(NSS)}	NSS hold time	Slave mode	2 T _{pclk}	-	ns
t _{w(SCKH)} t _{w(SCKL)}	SCK high and low time	Master mode, presc = 2	T _{pclk} -2	T _{pclk} +1	ns
t _{su(MI)} t _{su(SI)}	Data input setup time	Master mode	1	-	ns
		Slave mode	3	-	
t _{h(MI)} t _{h(SI)}	Data input hold time	Master mode	5	-	ns
		Slave mode	2	-	
t _{a(SO)}	Data output access time	Slave mode	0	3 T _{pclk}	ns
t _{dis(SO)}	Data output disable time	Slave mode	2 T _{pclk}	-	ns
t _{v(SO)}	Data output valid time	Slave mode(after enable edge)	0	20	ns
t _{v(MO)}	Data output valid time	Master mode(after enable edge)	-	5	ns
t _{h(SO)} t _{h(MO)}	Data output hold time	Slave mode(after enable edge)	2	-	ns
		Master mode(after enable edge)	1	-	
DuCy(SCK)	SPI slave input clock duty cycle	Slave mode	45	55	%

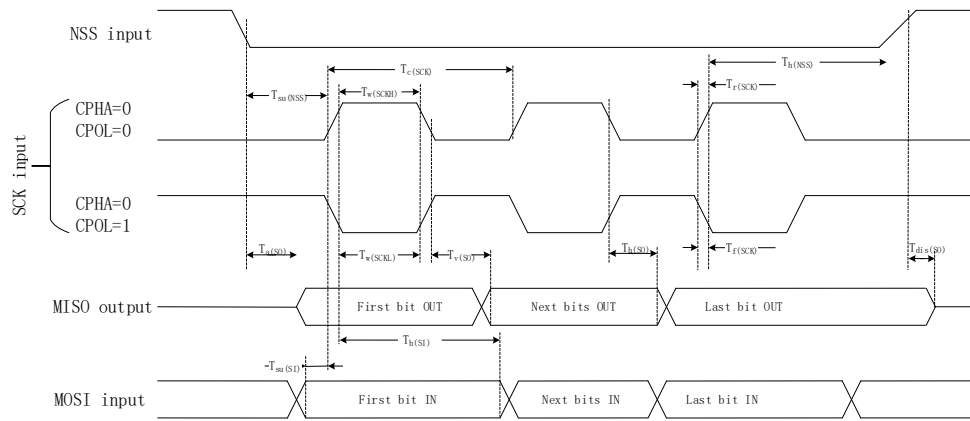


Figure 5-4 SPI timing diagram – Slave mode and CPHA=0

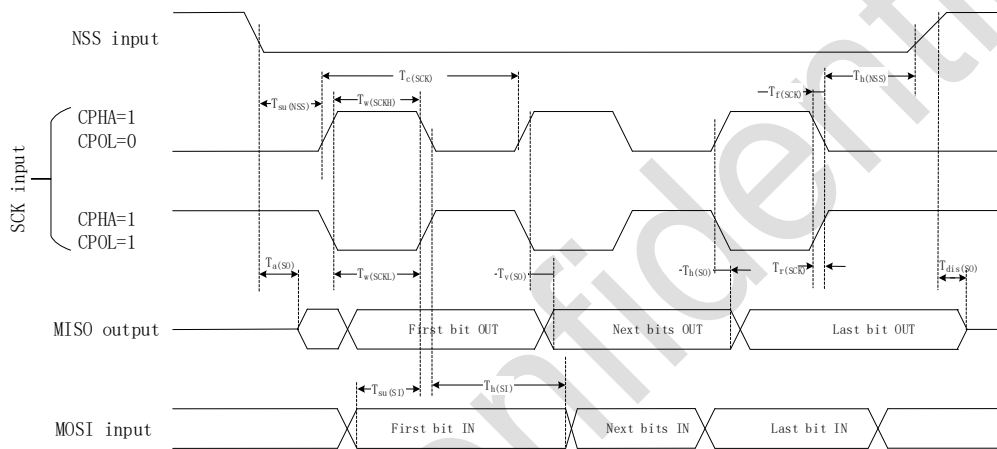


Figure 5-5 SPI timing diagram – Slave mode and CPHA=1

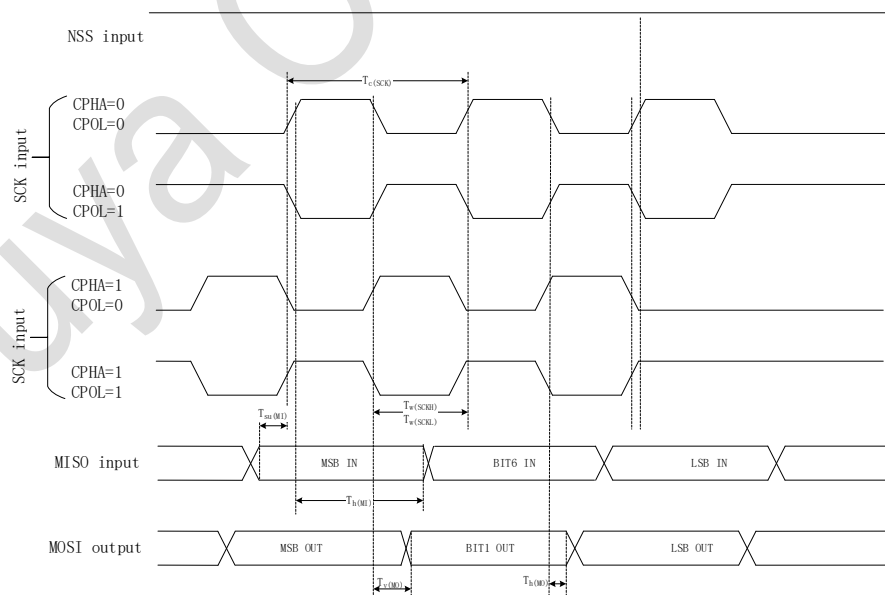
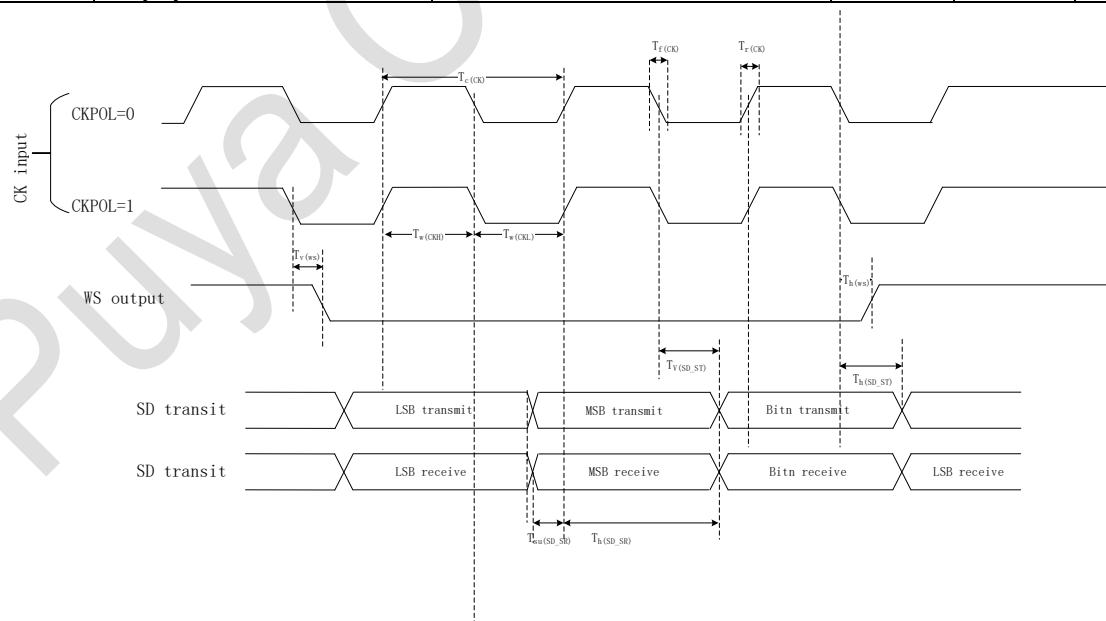
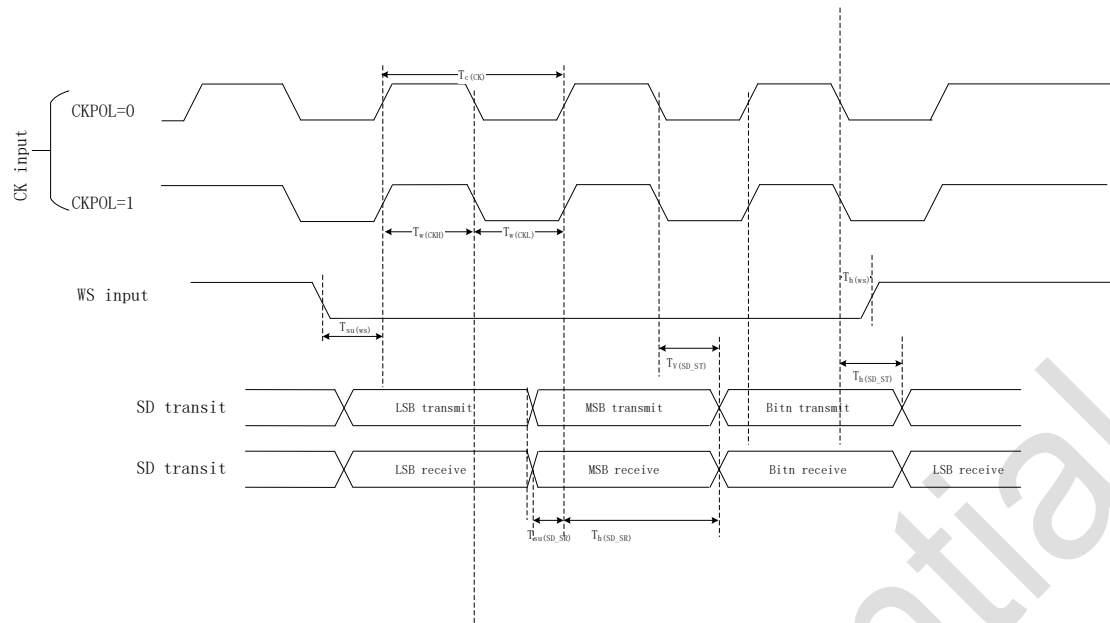


Figure 5-6 SPI timing diagram – Master mode

5.3.21.3. I²S characteristicsTable 5-40 I²S characteristics

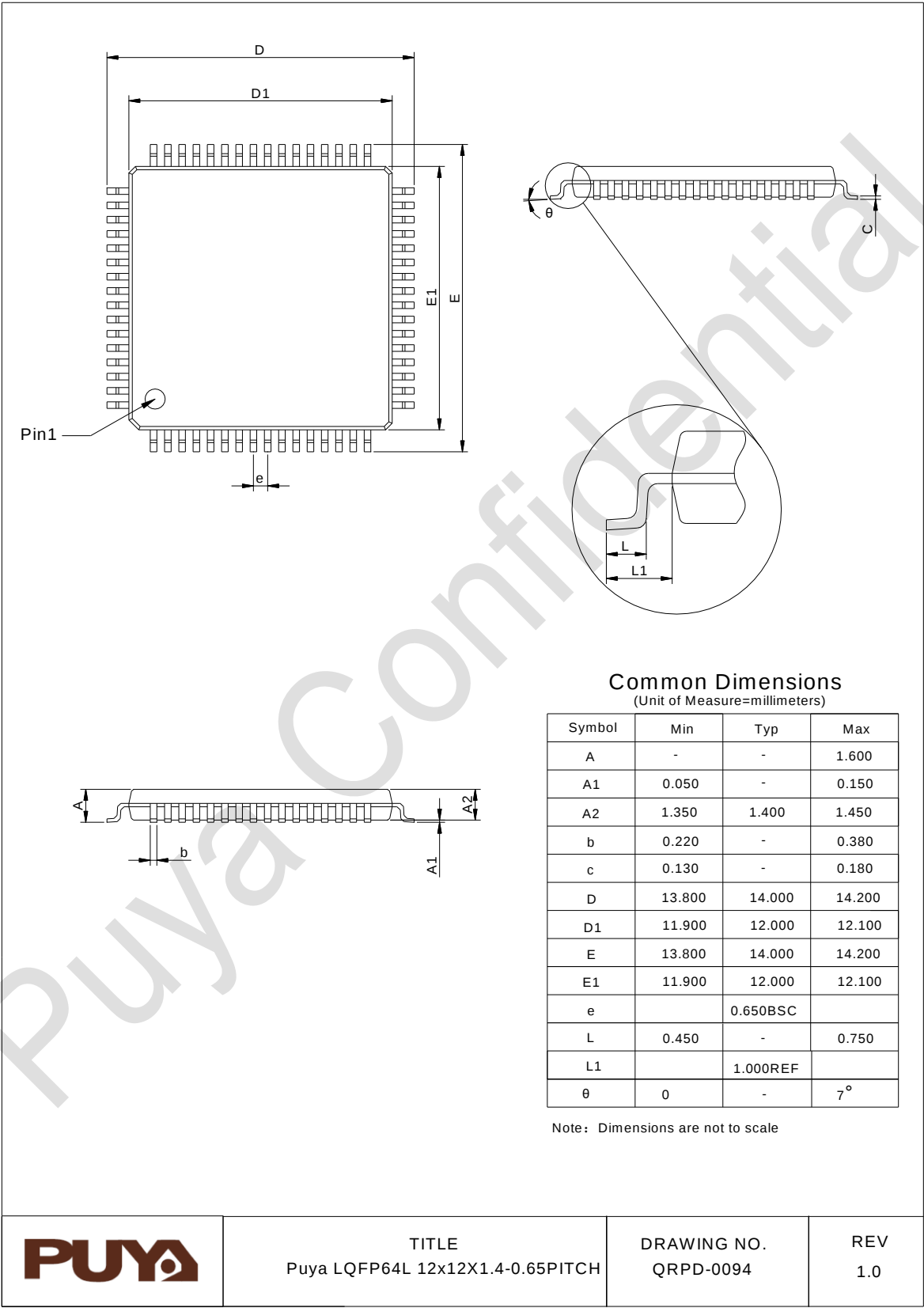
Symbol	Parameter	Conditions	Min	Max	Unit
f_{CK}	I ² S clock frequency	Master mode(data: 16 bits, audio frequency=48 kHz)	1.597	1.601	MHz
		Slave mode	0	7	
$t_{r(ck)}$	I ² S clock rise time	Capacitive load: $C_L = 15$ pF	-	5	ns
$t_{f(ck)}$	I ² S clock fall time	Capacitive load: $C_L = 15$ pF	-	6	
$t_{w(CKH)}$	I ² S clock high time	Master $f_{PCLK} = 16$ MHz, audio frequency = 48 kHz	306	-	
$t_{w(CKL)}$	I ² S clock low time	Master $f_{PCLK} = 16$ MHz, audio frequency = 48 kHz	312	-	
$t_{v(WS)}$	WS valid time	Master mode	2	-	
$t_{h(WS)}$	WS hold time	Master mode	2	-	
$t_{su(WS)}$	WS setup time	Slave mode	7	-	
$t_{h(WS)}$	WS hold time	Slave mode	1	-	
$t_{su(SD_MR)}$	Data input setup time	Master mode	11.5	-	
$t_{su(SD_SR)}$		Slave mode	2	-	
$t_{h(SD_MR)}$	Data input hold time	Master mode	0	-	
$t_{h(SD_SR)}$		Slave mode	0	-	
$t_{v(SD_MT)}$	Data output valid time	Master mode	-	17	
$t_{v(SD_ST)}$		Slave mode	-	9	
$t_{h(SD_MT)}$	Data output hold time	Master mode	4	-	
$t_{h(SD_ST)}$		Slave mode	6	-	
DuCy(sck)	I ² S slave input clock duty cycle	Slave mode	45	55	%

Figure 5-7 I²S timing diagram – Master mode(Philips protocol)

Figure 5-8 I²S timing diagram – Slave mode(Philips protocol)

6. Package information

6.1. LQFP64(12*12) package size



7. Ordering information

	PY	32	F	040	R1	B	T	7	x	-	E	P
Company												
Product family	ARM [®] based 32-bit microcontroller											
Product type	F = General purpose											
Sub-family	040 = PY32F040xx											
Pin count	R1 = 64 pins Pinout1											
User code memory size	B = 128 KB											
Package	T = LQFP											
Temperature range	7 = -40 °C to +105 °C											
Options	xxx = code ID of programmed parts(includes packing type) blank = tray packing											
Delimiter character												
Version	E = Wafer version											
Customer ID	P = Customized for Panasonic											

8. Version history

Version	Date	Updated record
V1.0	2025.07.15	Initial version



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